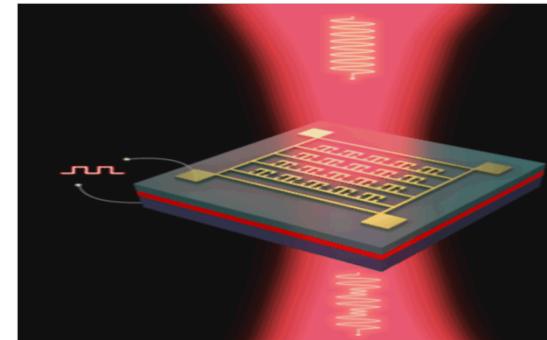
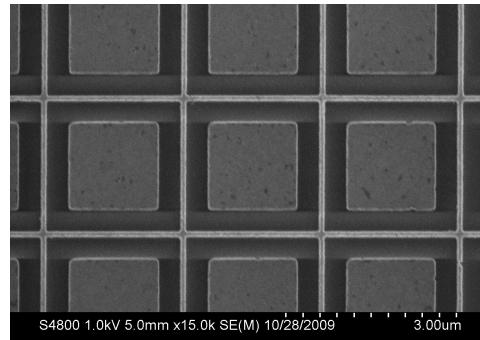
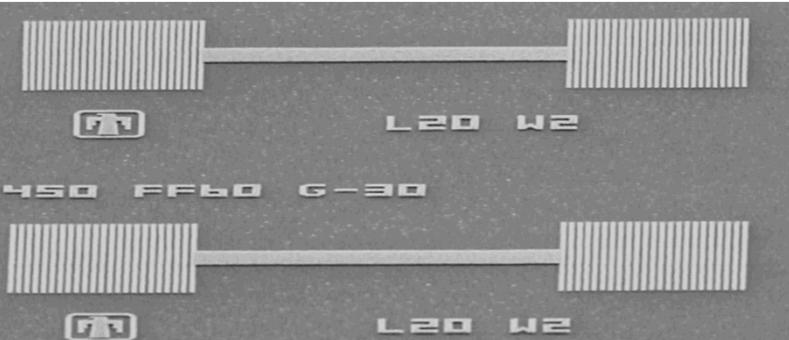


Exceptional service in the national interest



Surface Wave Enabled Infrared Detectors (and other photonic and plasmonic devices)

David W. Peters
dwpeter@sandia.gov



Sandia National Laboratories is a multi-program laboratory managed and operated by Sandia Corporation, a wholly owned subsidiary of Lockheed Martin Corporation, for the U.S. Department of Energy's National Nuclear Security Administration under contract DE-AC04-94AL85000. SAND NO. 2011-XXXX

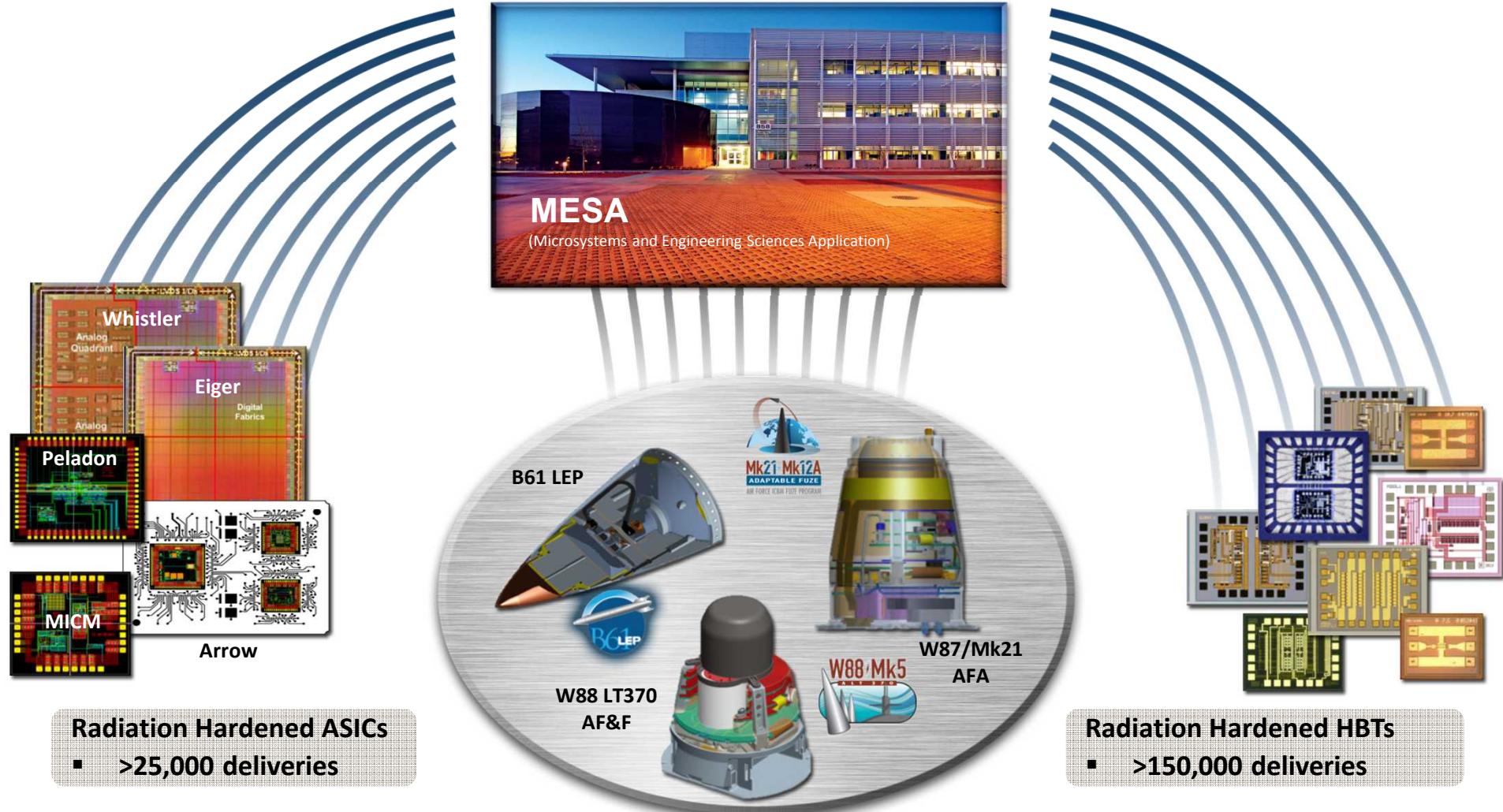
Sandia National Laboratories

1950s	1960s	1970s	1980s	1990s	2000s	2010s
NW production engineering & manufacturing engineering	Development engineering	Multiprogram laboratory	Missile defense work	Post-Cold War transition	Expanded national security role post 9/11	LEPs New START



- DOE FFRDC: Initially Z-division of Manhattan Project (Non-nuclear components, weaponization of NEP)
- **National security tech transition:** Gov't agencies (and/or academia) → SNL → Industry
- Our Big 3: Non-compete with Industry, Fairness of Opportunity, No Organizational Conflict of Interest
- Managed by LMC (but see OCI above)
- CRADAs with many defense contractors, many STTRs & SBIRs, BAA response teaming
- Experience handling sensitive & proprietary information
- DOE supports our “Strategic Partnership Projects” (with industry & other gov’t agencies (OGAs))

Manufactures strategic radiation-hardened trusted components for nuclear weapons



MESA: 400,000 ft² Complex with >650 Employees in a Secure Facility

- Trusted Digital, Analog, Mixed Signal & RF Integrated Circuits Design & Fabrication
- Custom IC Design
 - Secure microcontrollers
 - Sensor Readout ICs
 - Analog/Digital/RF
 - IBM Trusted Foundry
 - Tamper Resistant
- Micromachining
- RAD Effects and Assurance
- Failure Analysis, Reliability Physics
- Test & Validation
- 3-D Integration Features

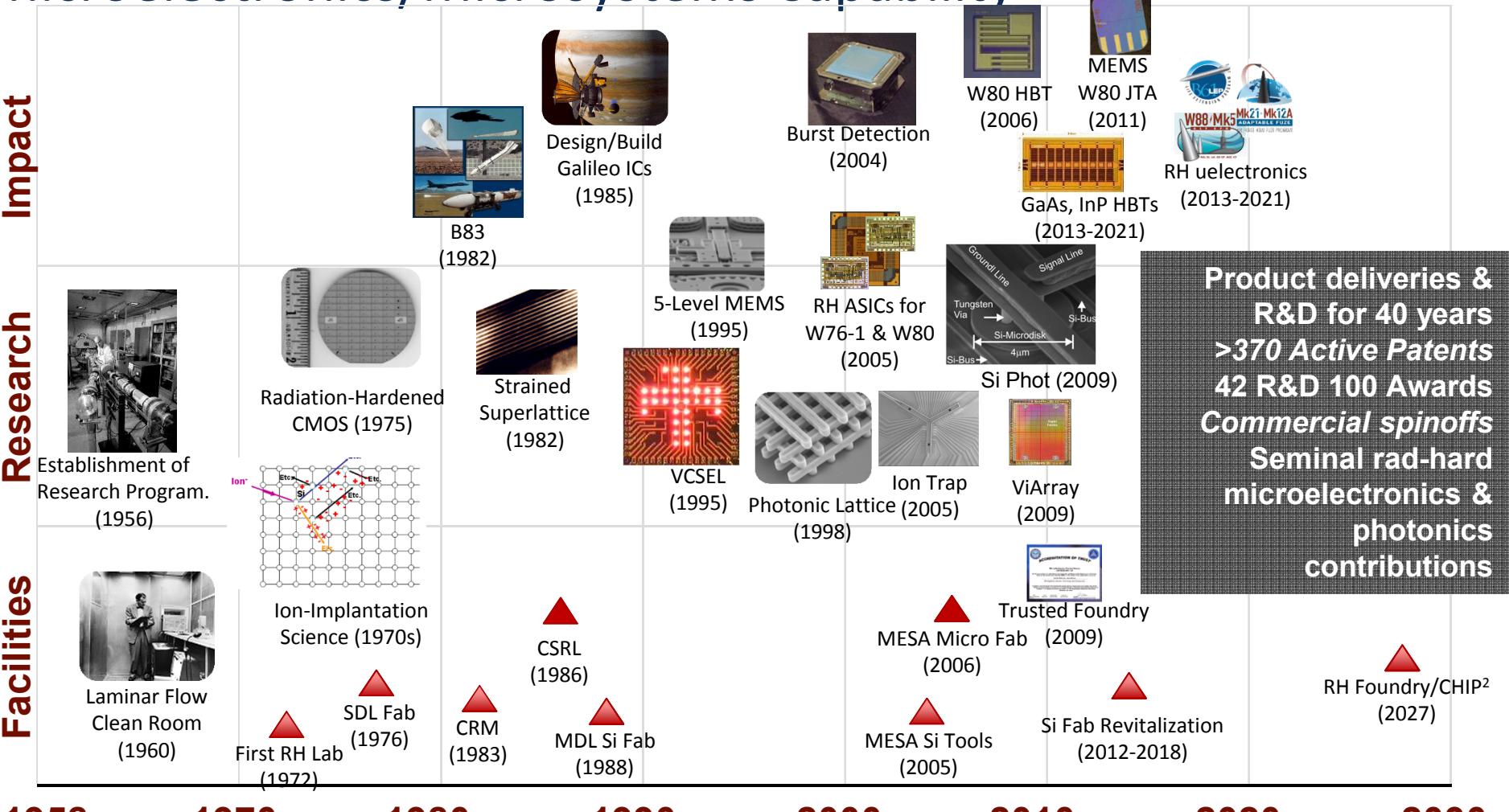


- Advanced Computation
- Modeling & Simulation
- COTS Qualification
- Advanced Packaging
- Custom Electronic Components
- System Design & Test

MESA is an FFRDC-based development and production facility for any microsystem component or technology that cannot or should not be obtained commercially.

- Compound Semiconductor Epitaxial Growth (UV-THz)
- Photonics: Si & III-V
- MEMS, VCSELs, Plasmonics
- Specialized Sensors, FPA
- Materials Science, Graphene
- Nanotechnology, Chem/Bio
- Heterogeneous-Technology Integration & Processing
- III-V Semiconductor Devices
 - Neutron-Immune HBT
 - Rad-hard Optical Links
 - Solid-State RF Devices
 - GaN Power Electronics

R&D enables and sustains Sandia's Radiation-Hardened Microelectronics/Microsystems Capability



MISSION: Invent and mature integrated circuit and microsystems technologies that provide differentiation and impact for NW and other national security missions.

Trusted Advanced Pathfinder Products: Si Photonics

2014

balanced homodyne
resonant wavelength
stabilization > 55C

2013

Si Photonics MPW
(CIAN NSF ERC)

2012

24 GHz Si TW MZM

2011

45 GHz Ge Detector

2010

3 fJ/bit resonator
modulator, 1V-cm
MZM

2009

wavelength tunable
rings over 35 nm

2008

2.4 ns Wavelength
selective switch

2007

MicroDisk resonator
infrared detector

2005

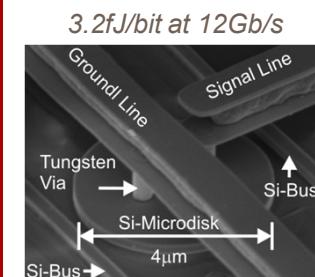
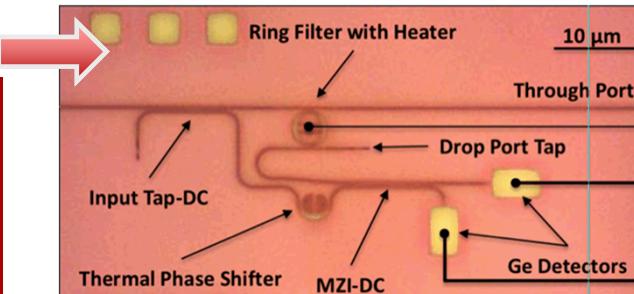
Si_3N_4 low-loss
waveguides

2000

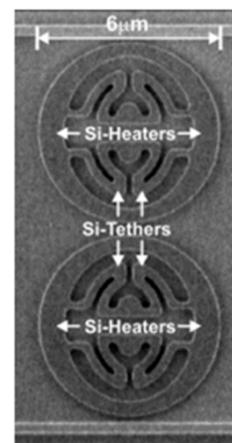
$SiON / SiO2$
(Clarendon Photonics)

1990s

Si PhC & Optical MEMS

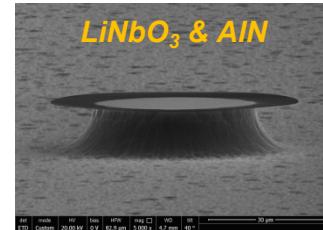


Resonant Optical
Modulator/Filter

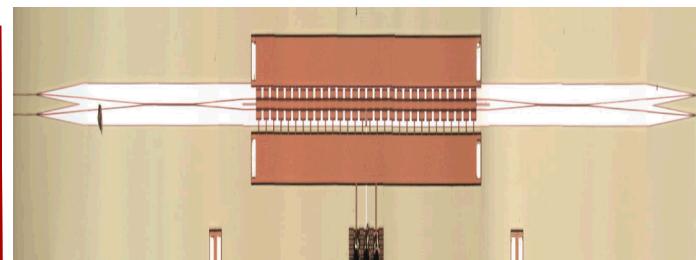


Tunable Resonant
Filter

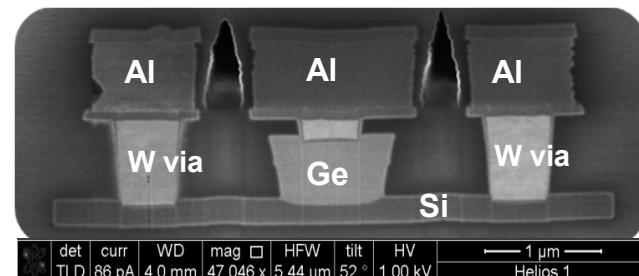
MEMS process
for additional
capability



$LiNbO_3$ & AlN



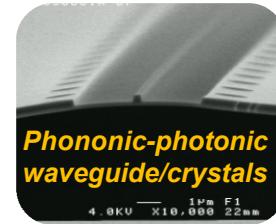
24 GHz 0.7V-cm Travelling Wave
MZI Modulator



45 GHz High-speed Ge Detector on Si



Suspended Si/SiN
resonators

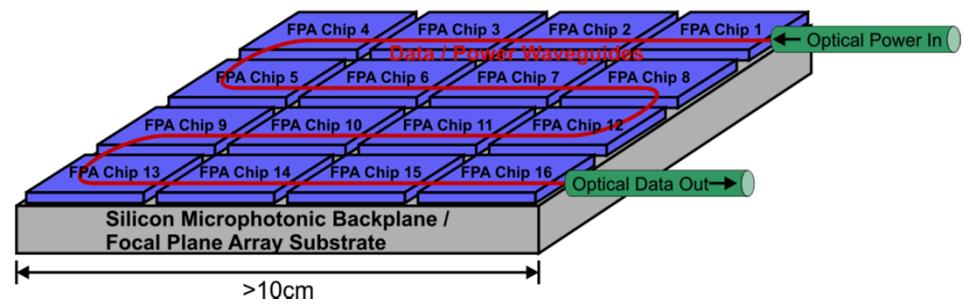
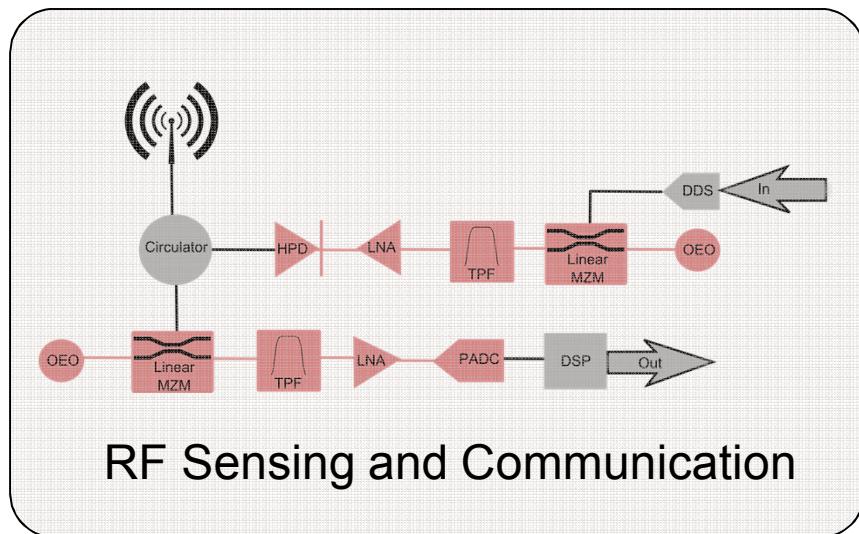
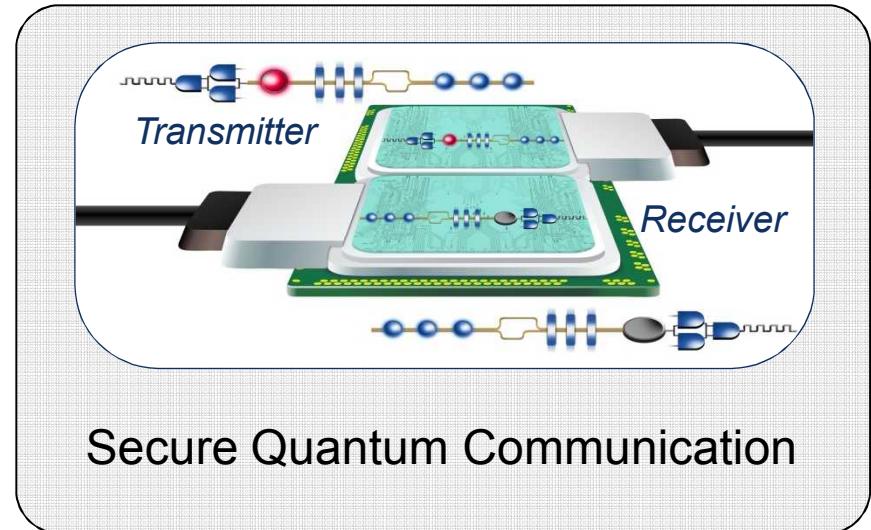


Phononic-photonic
waveguide/crystals

Photonics Enabled System Applications

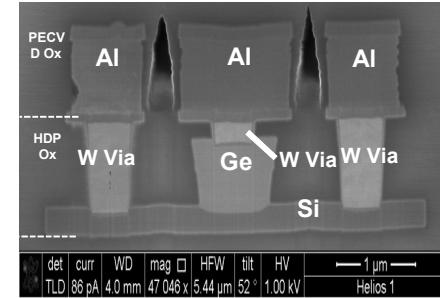
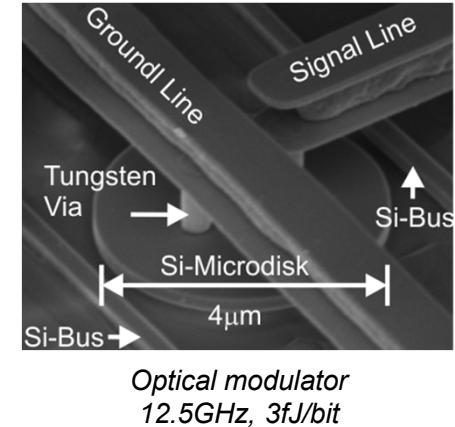
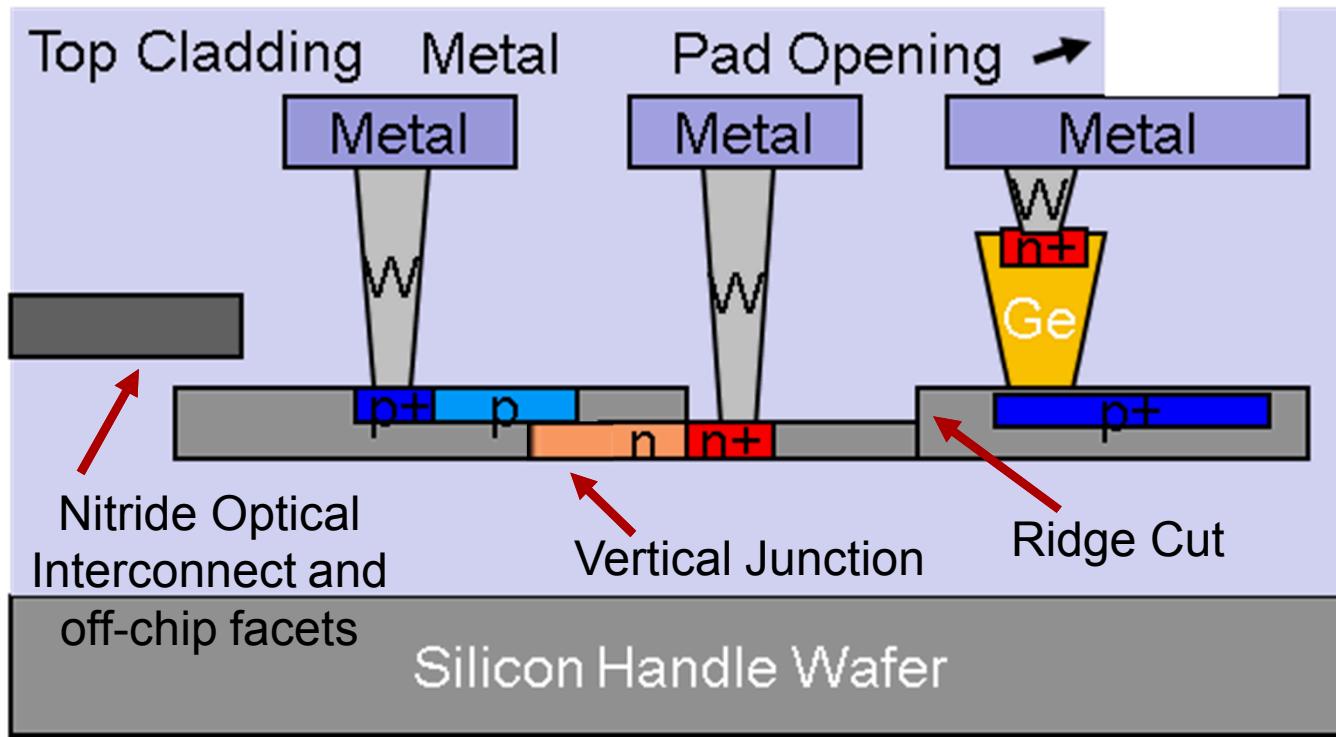


High Performance Computing



Focal Plane Array Communications

SNL Silicon Photonics Process



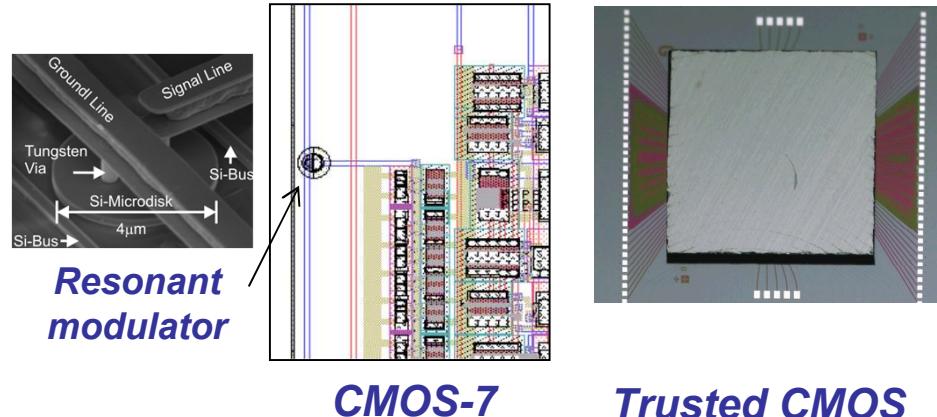
- CMOS compatible
- Passive and active photonics devices
 - Silicon and silicon nitride waveguides, couplers, splitters, gratings, filters, modulators, Germanium detectors, switches, etc.

Si Photonics for Detector Communication

Silicon Photonics Capabilities:

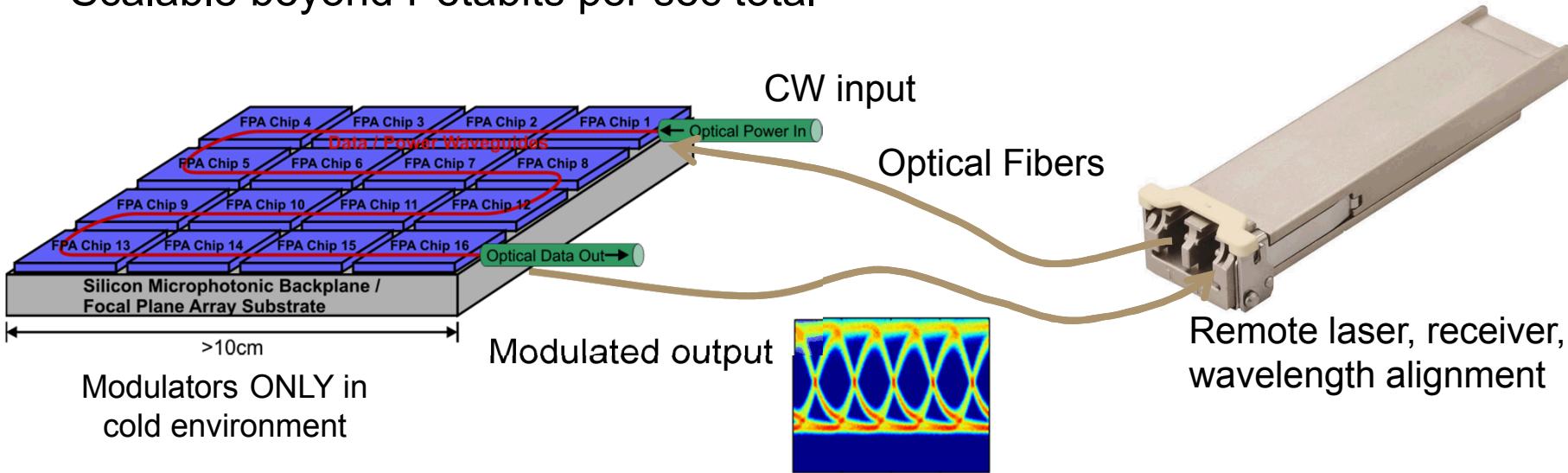
- Modulator energy < 1 fJ/bit
 - 10,000 X lower than commercial optical transceivers in radiation environment
- Low voltage CMOS drive < 0.5V
- Bit rates > 10 Gb/s, future 25 Gb/s
- DWDM: > 1 Tb/s per fiber connection
- Scalable beyond Petabits per sec total

Si Photonics-CMOS Integration *Monolithic* *Flip-chip bonding*



CMOS-7

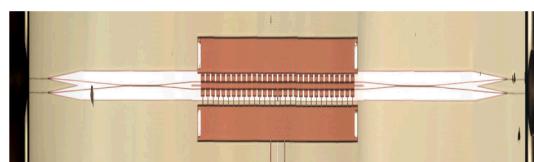
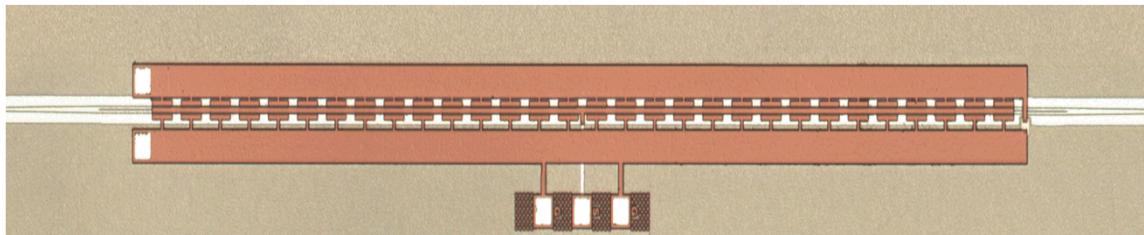
Trusted CMOS



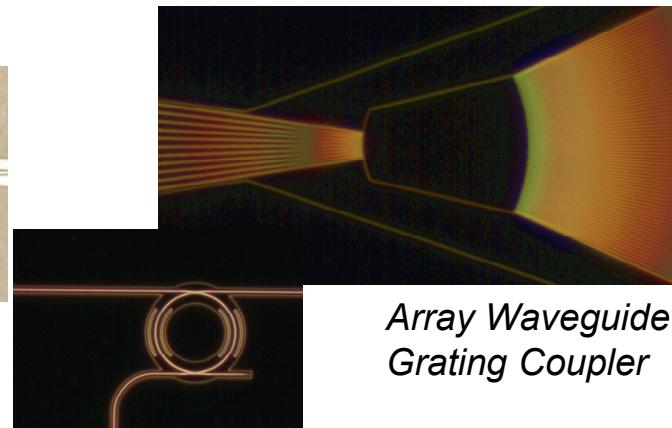
SNL RF Si Photonics Technologies

Silicon Photonics

Optical modulation and spectrum analysis up to 100GHz



*Mach-Zehnder Modulator with Traveling-Wave Electrodes
20GHz, $V_{pi} \times L = 0.8 \text{ Vcm}$*

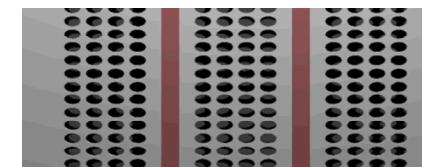
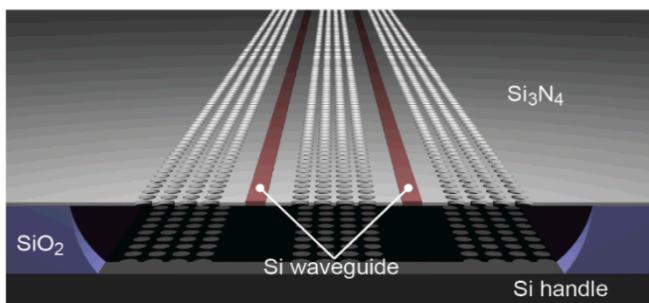


Micro-ring Tunable Filter (MHz – GHz)

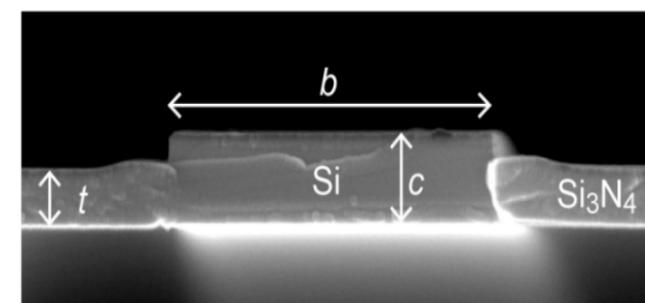
Array Waveguide Grating Coupler

Silicon / SiN Nano-Optomechanics

Photon-phonon transduction for signal processing with up to 20GHz BW



Suspended Si waveguides with phononic crystals

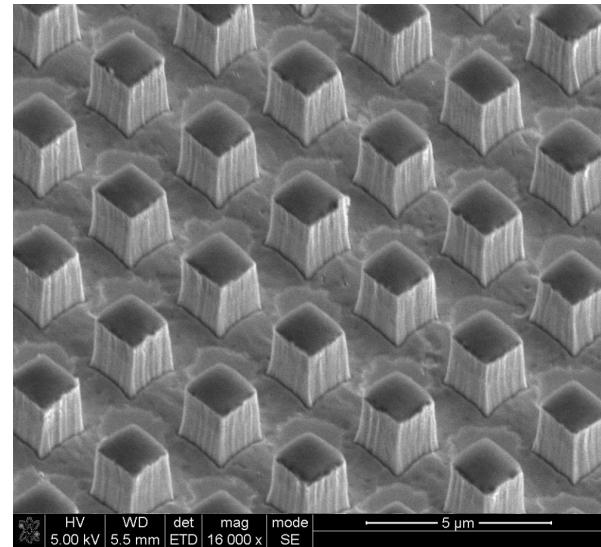


- New paradigm for RF signal processing (ex. filtering) in optical domain to reduce size, weight, and power, and improve performance

Dielectric and Metallic Metamaterials

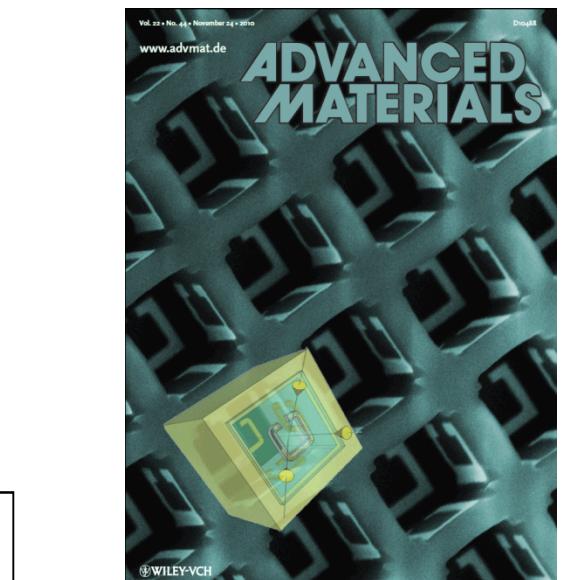
First ever all dielectric infrared metamaterial:

- best route to low loss metamaterials
- demonstrated negative permeability and permittivity at IR wavelengths
- new resonator designs for negative index behavior



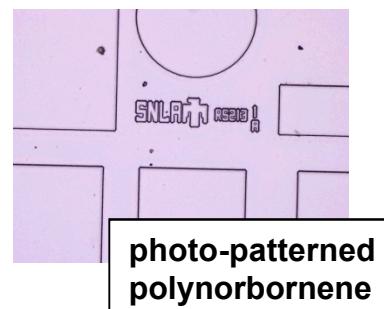
Membrane Projection Lithography:

- a new 3D fabrication tool
- metallic resonators with out-of-plane currents
- isotropic metamaterials.

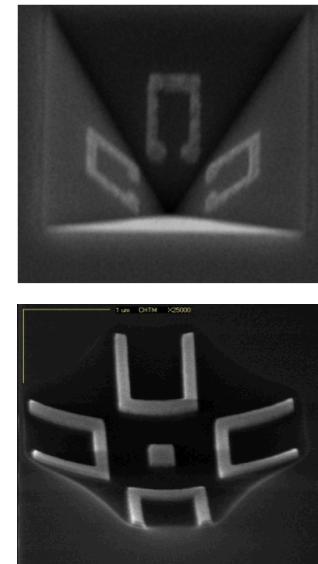
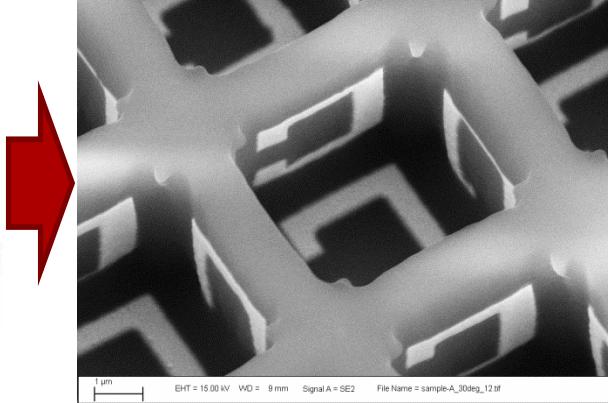
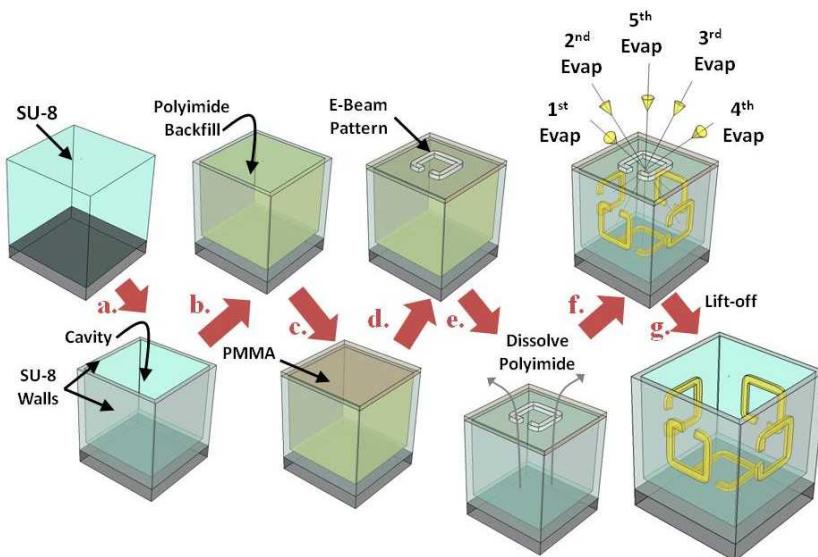


Polynorbornene:

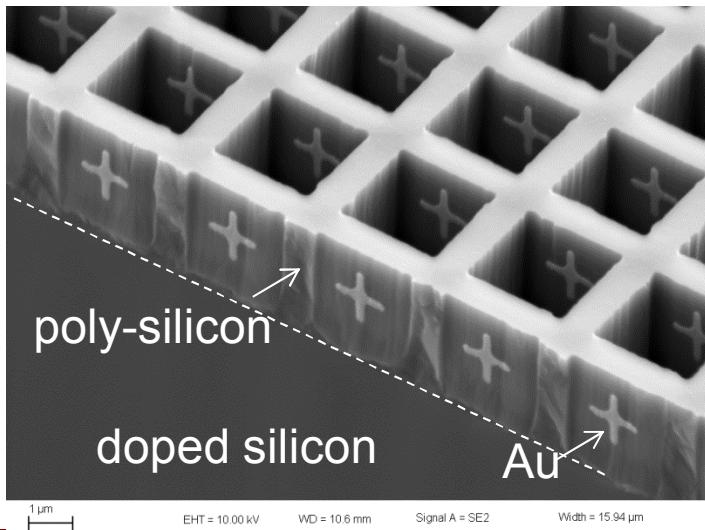
- SU8 of the IR
- low IR loss polymer
- photo cross-linkable
- wide ranging applications



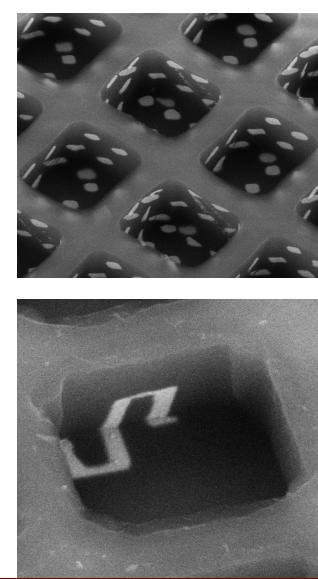
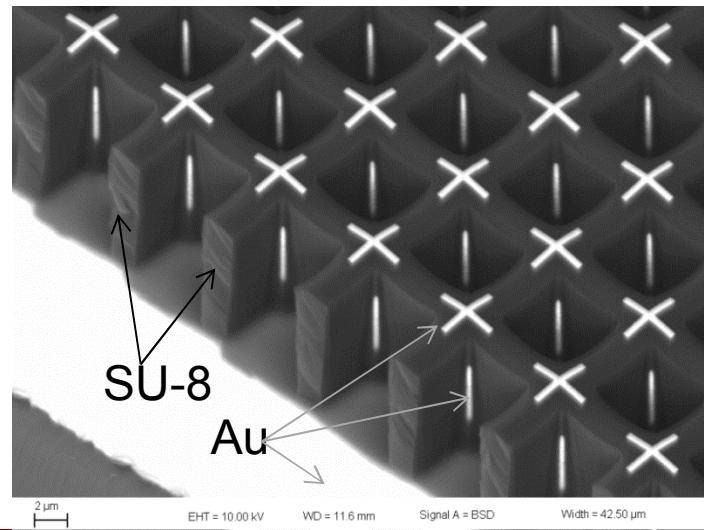
Membrane Projection Lithography



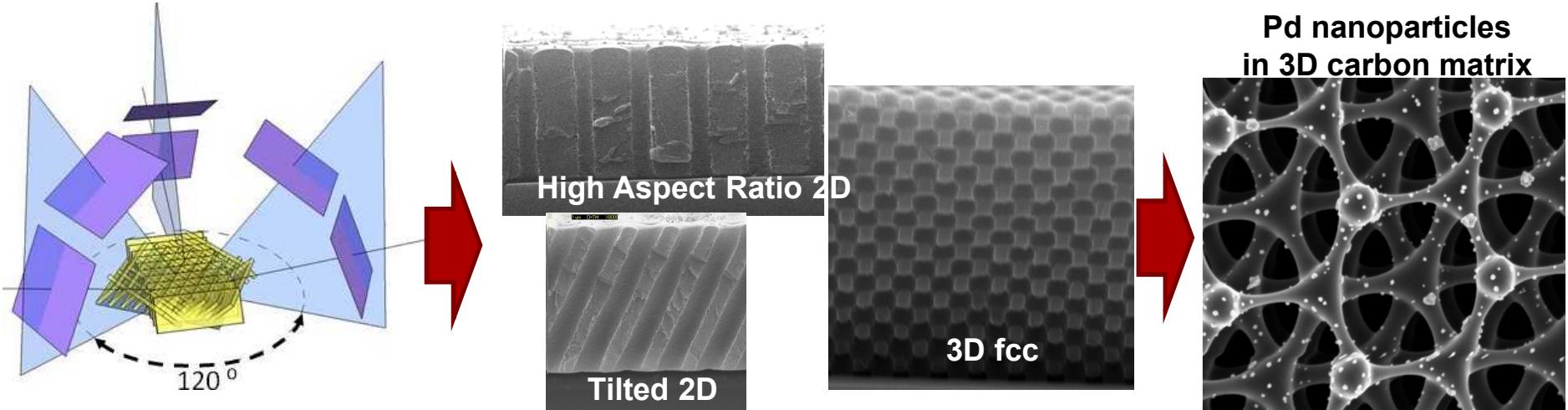
CMOS Compatible Inorganic Material Set



Polymer-Based Material Set



3D Pyrolyzed Carbon

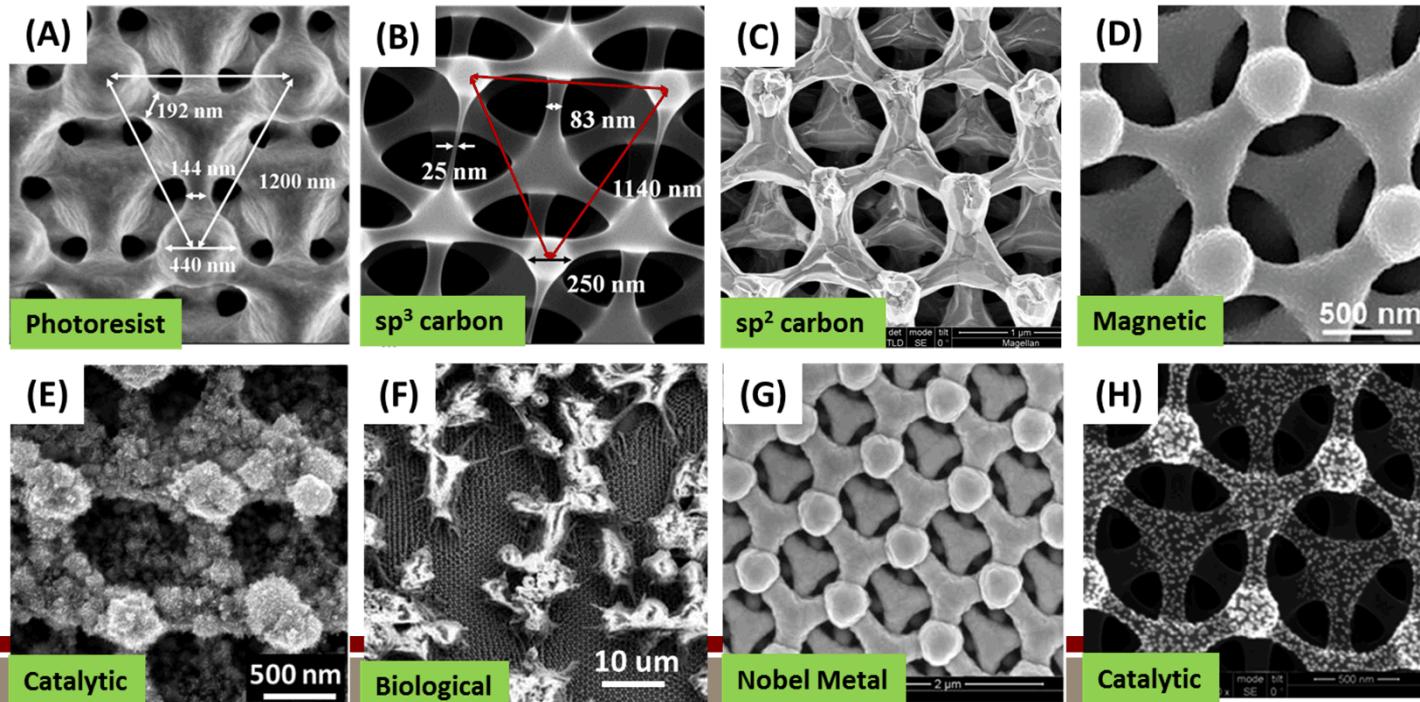


Interferometric Lithography

Resist Patterns

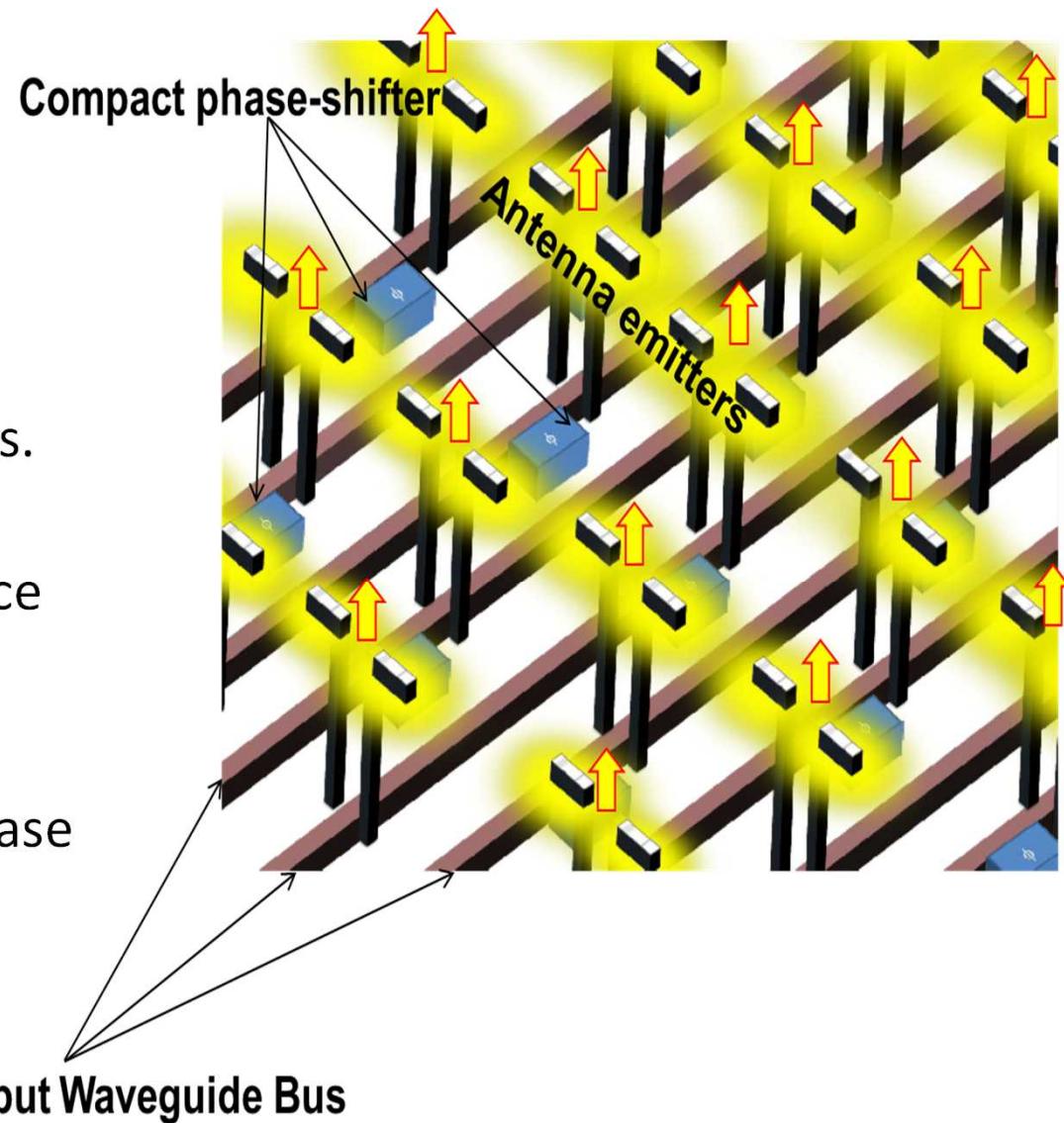
Carbon Scaffold

Scaffolds readily modified using a variety of methods and materials



Free-Space Infrared Communication

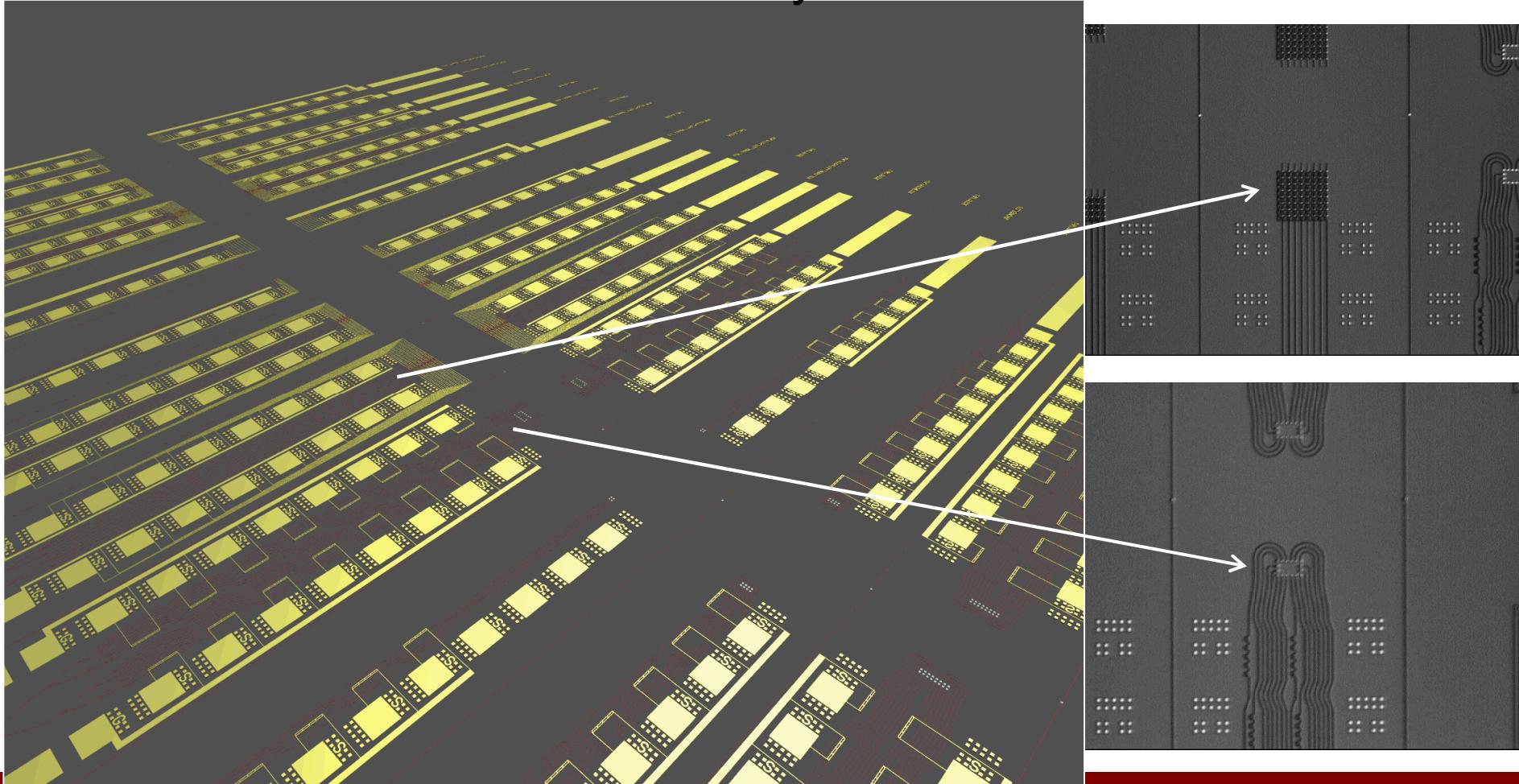
- Use Si Photonics Platform
 - Low loss dielectric waveguides. (light distribution)
 - Integrate compact waveguide phase shifters.
 - Use metallic antenna to radiate efficiently (surface normally)
- Place in periodic array
 - Electronically control phase of each antenna



Phased Array Test-Chip

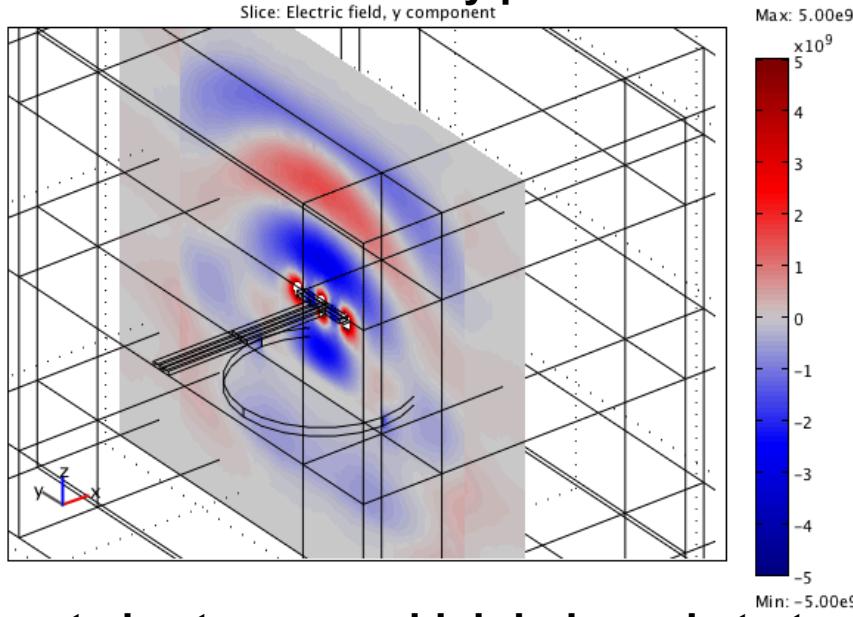
Key elements:

1. Integrated waveguide phase shifters
2. Plasmonic antenna arrays

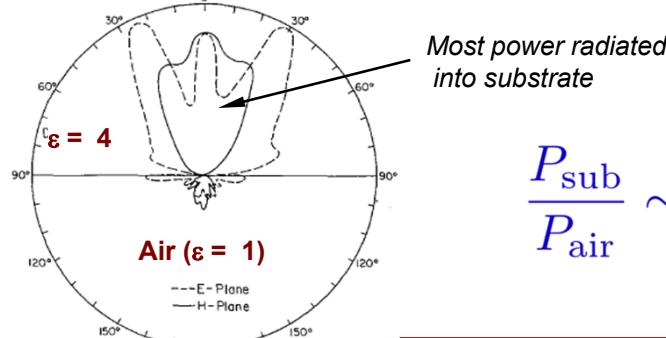


Radiation Pattern of MIM-fed Antenna

Surface-normal radiation by planar antennas



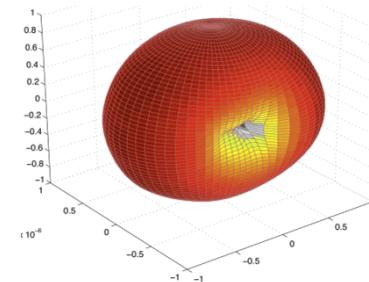
Integrated antennas on high-index substrates



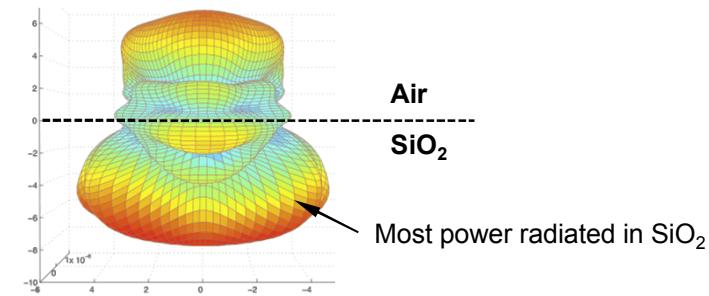
$$\frac{P_{\text{sub}}}{P_{\text{air}}} \sim \epsilon^{3/2}$$

Ground-plane is necessary !

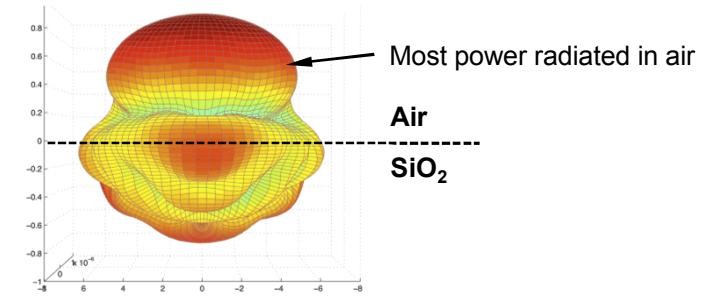
MIM-fed dipole in Air



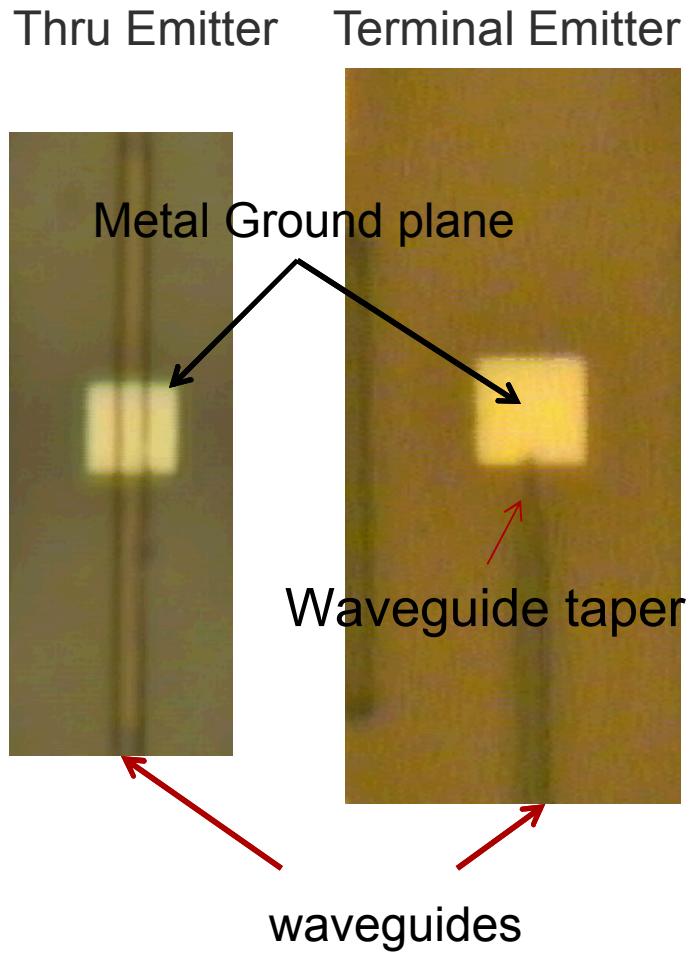
MIM-fed dipole in on SiO_2 (No ground-plane)



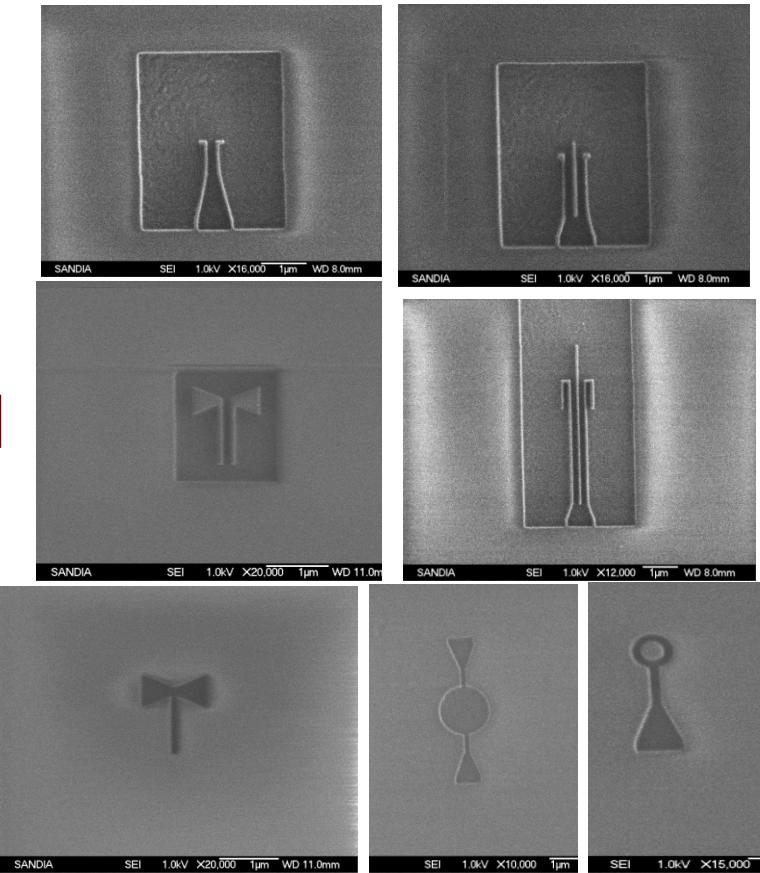
MIM-fed dipole in on SiO_2 (With ground-plane)



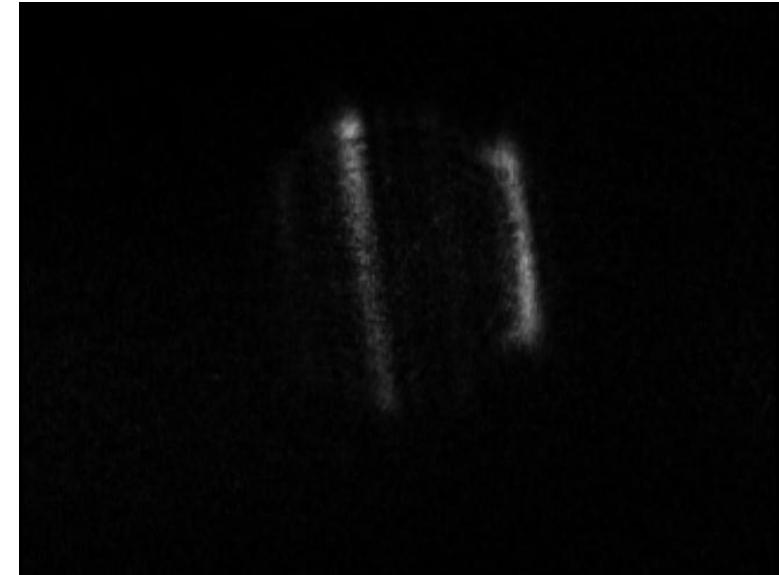
E-Beam Nanoantenna Template



E-Beam nanoantenna



Electronically Phase Controlled 1x8 Array



Demonstrated an optical phased array beam steering system comprised of

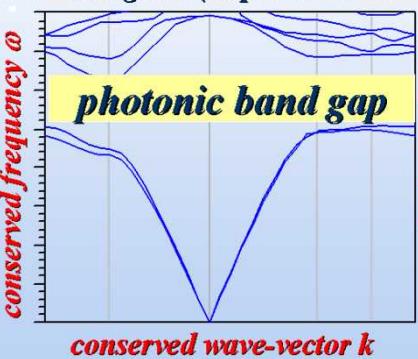
- Periodic array of plasmonic antennas
- Individually electronically addressed waveguide phase shifters
(2π phase shift)
- Surface normal emission and steering at fixed wavelength.

Photonic Crystals (PhCs):

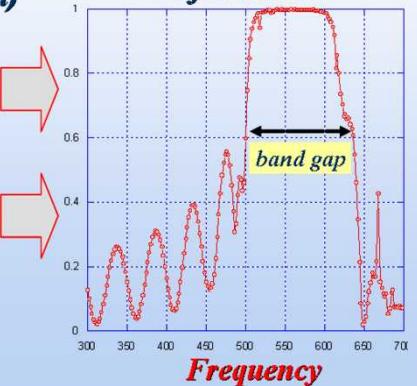
Molding the Flow of Light at the Nano Scale

Photonic crystals create bandgaps where photons are forbidden to propagate.

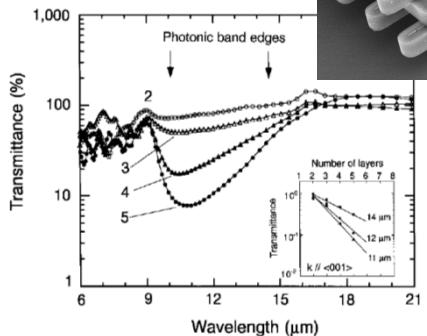
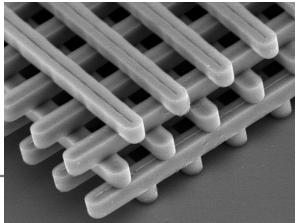
Band diagram (dispersion relation)



Reflectance



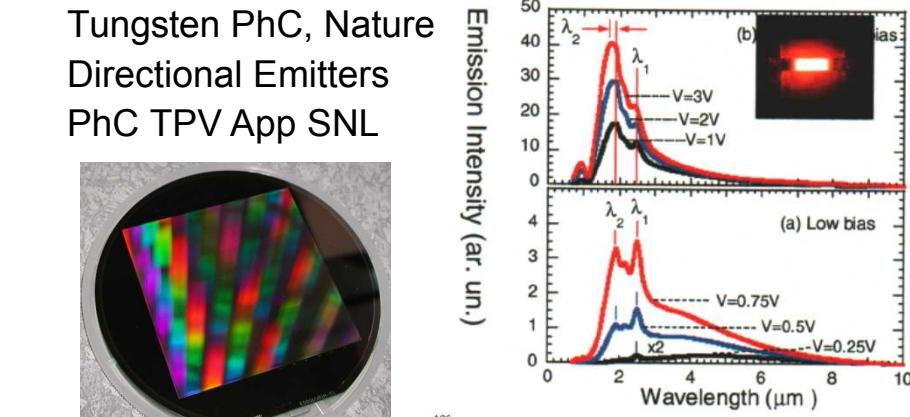
1st 3D Silicon PhC 1998-99



PhC Near Field TPV 2009
Thermal Energy Harvesting
Renewable Energy

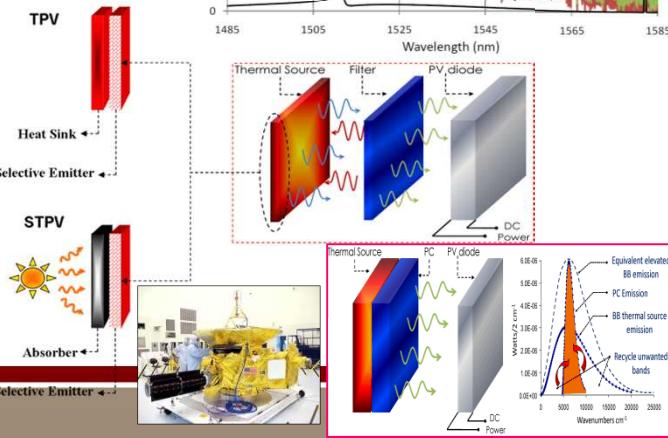
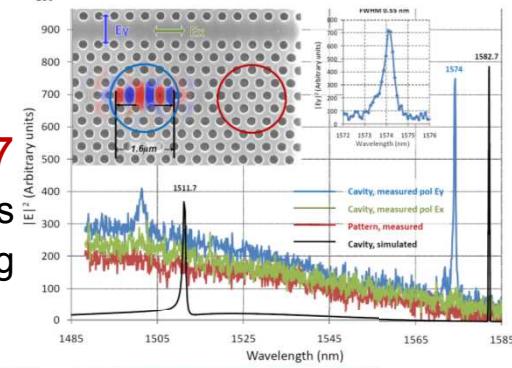
1st 3D IR Metallic PhC 2001-04

Tungsten PhC, Nature
Directional Emitters
PhC TPV App SNL



PhC Cavity QED 2007

Single photon sources
Quantum computing

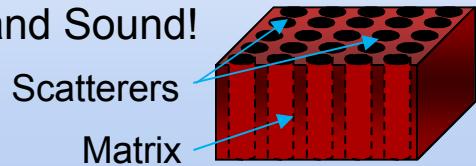


Phononic Crystals (PnCs):

Phonon Manipulation at the Micro and Nano Scale

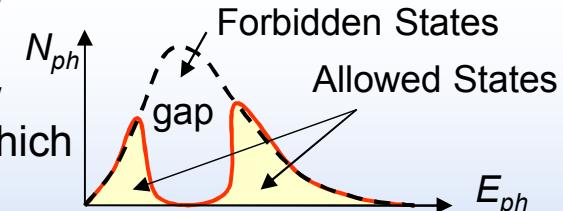
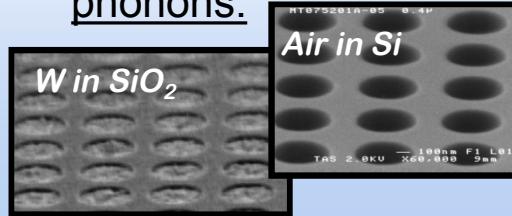
Phonons (What?)

- The quantum mechanical rendering of lattice vibrations (normal modes)
- The quanta of mechanical oscillations
- Heat and Sound!



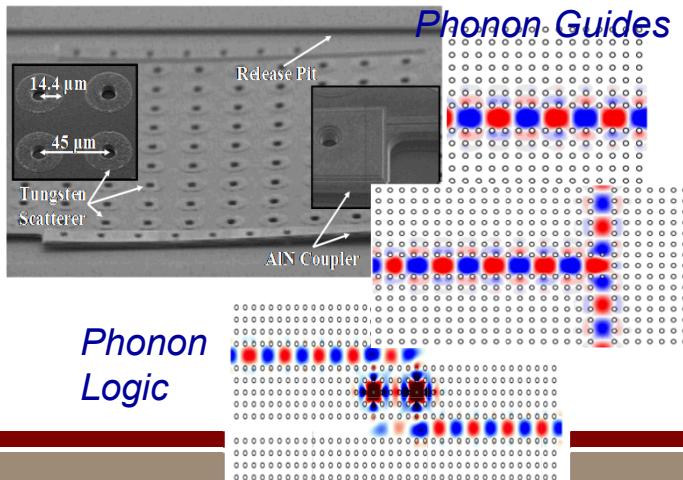
Phononic Crystals (How?)

Array of high impedance scattering centers in a low impedance background which exhibits stop bands for phonons.



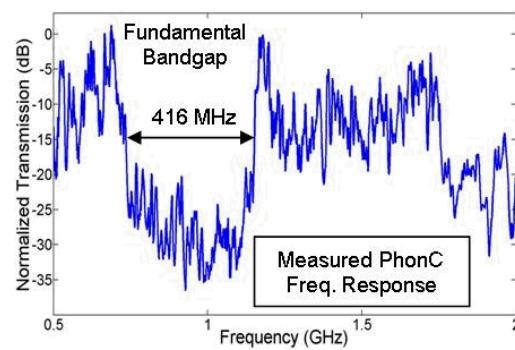
2007 1st MHz PnC

- Solid-Solid material sets
- RF Applications
- PnC-PhC Transformation



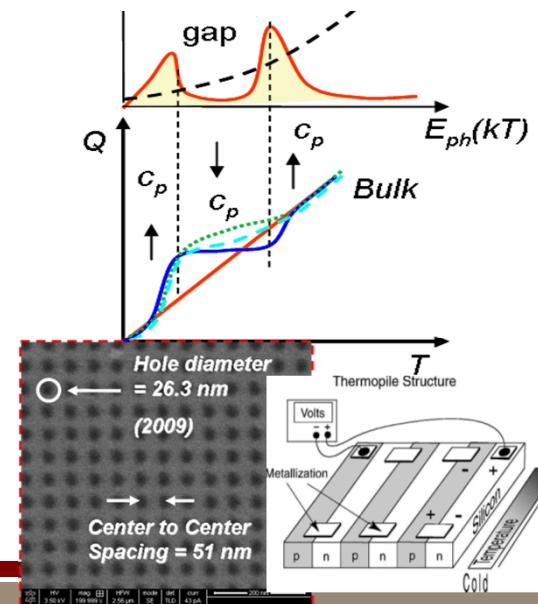
2008 1st GHz PnC

- Low loss RF devices and resonators
- RF communications, radars and spectral sensors



2009 1st THz PnC

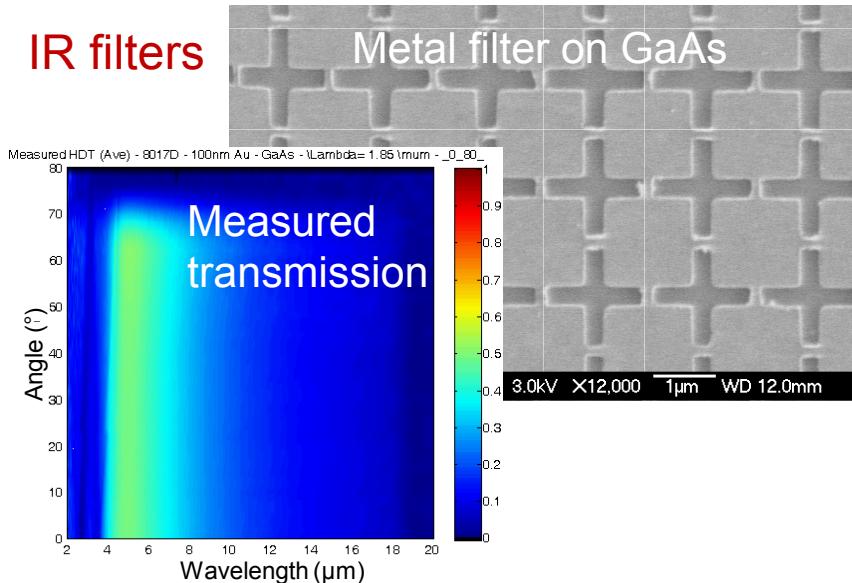
- Engineer thermal properties
- Thermal management
- Thermal energy scavenging
- TE cooling



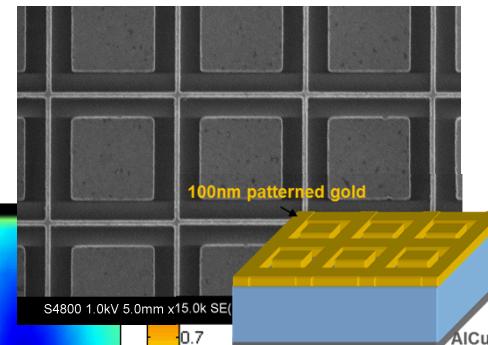
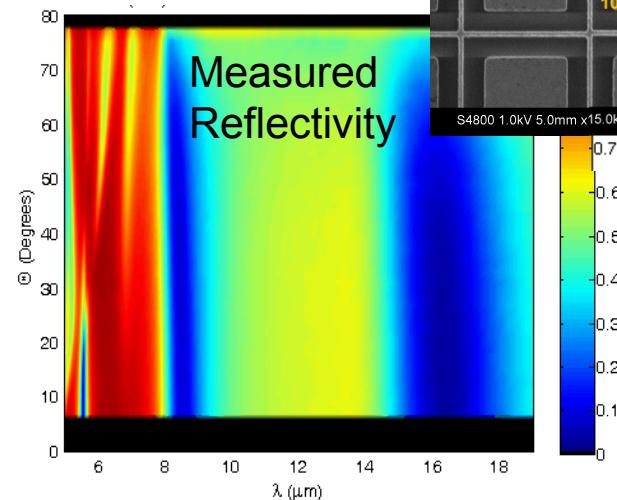
Planar Metallic Infrared Devices

Metal Optics for New Capabilities

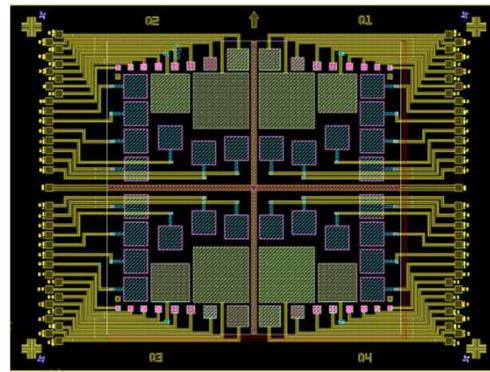
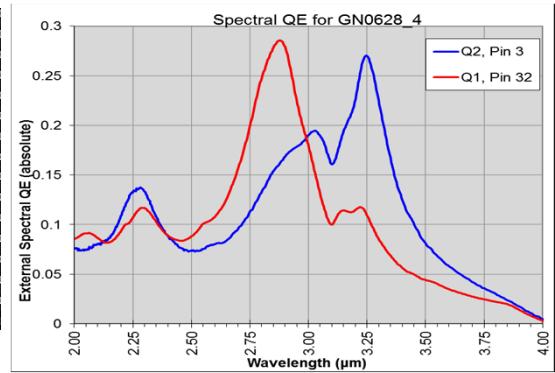
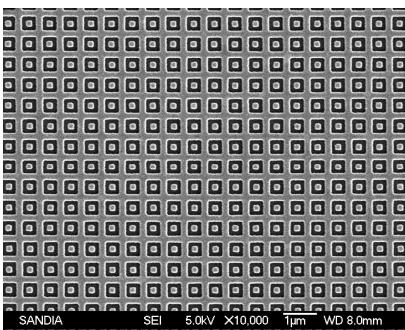
IR filters



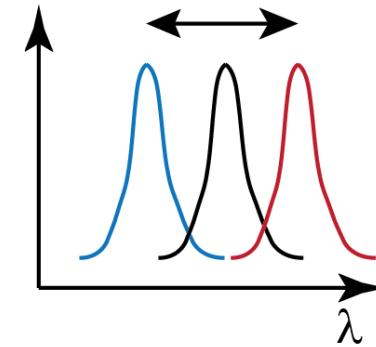
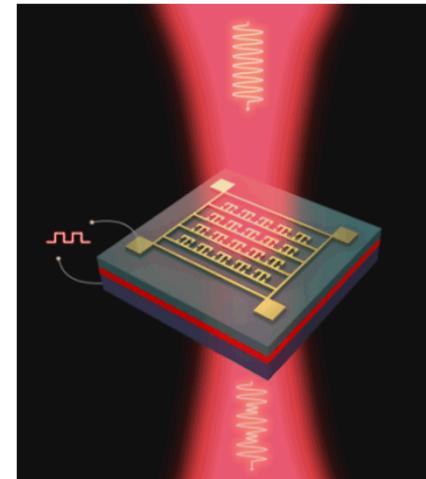
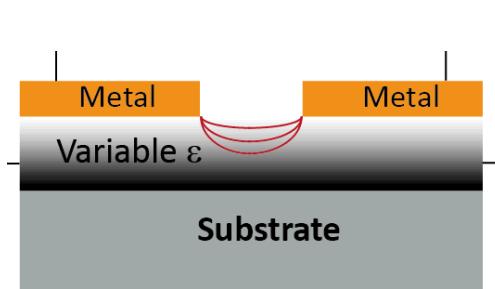
Perfect Absorbers/ Emitters



Next-Gen Low-Noise IR Detectors



Electrically Tunable Metamaterials for Agile Filtering in the Infrared



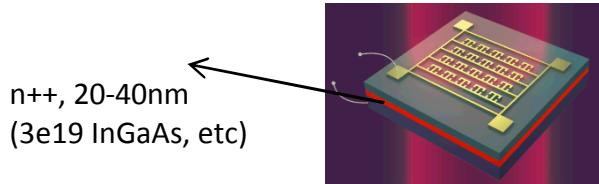
By controlling the interaction between planar metamaterials and semiconductors we created voltage tunable IR filters.

Specs:

- Mid to long wave IR
- Pixel size: $5\mu\text{m}^2$ and up
- Tuning by 1-2 FWHM
- $Q \sim 10-20$
- Voltage $< 10\text{V}$
- Made from III-V semiconductors

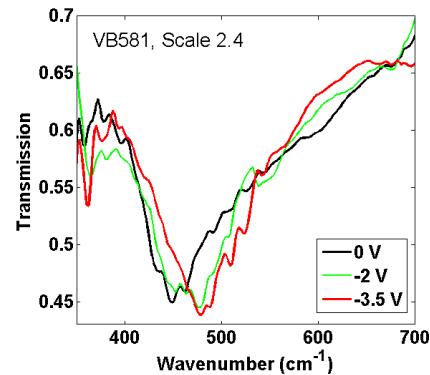
Two Voltage-Controlled Tuning Mechanisms

- Interaction with plasmons in highly doped semiconductor layers

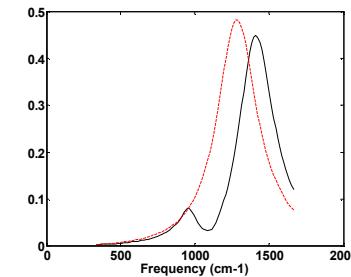


Nano Letters 13, 5391 (2013)

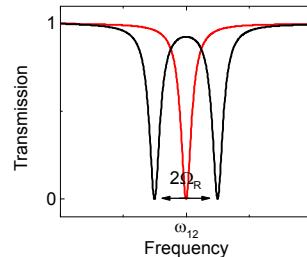
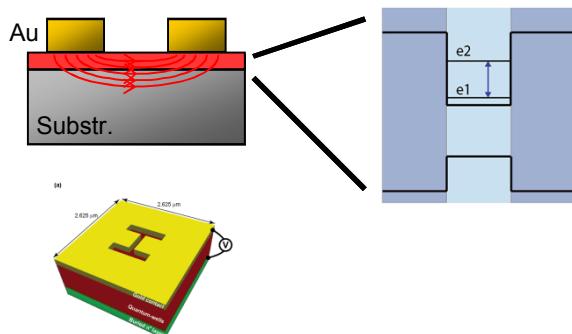
Preliminary results, long wave IR



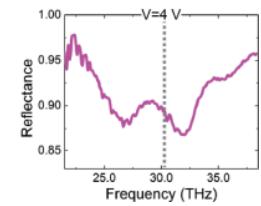
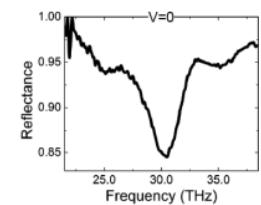
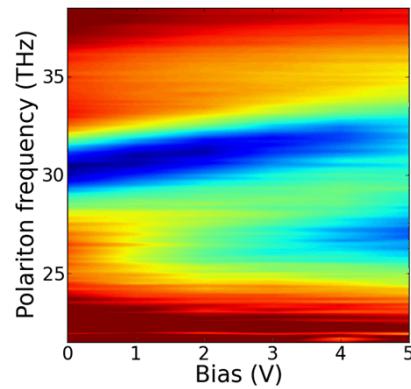
Recent modeling:



- Interaction with intersubband transitions in quantum wells



Preliminary results, thermal IR



Nature Communications 4, (2013) ; *APL* 103, 263116 (2013)

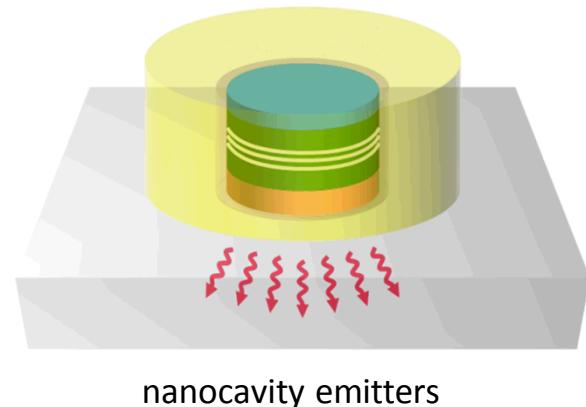
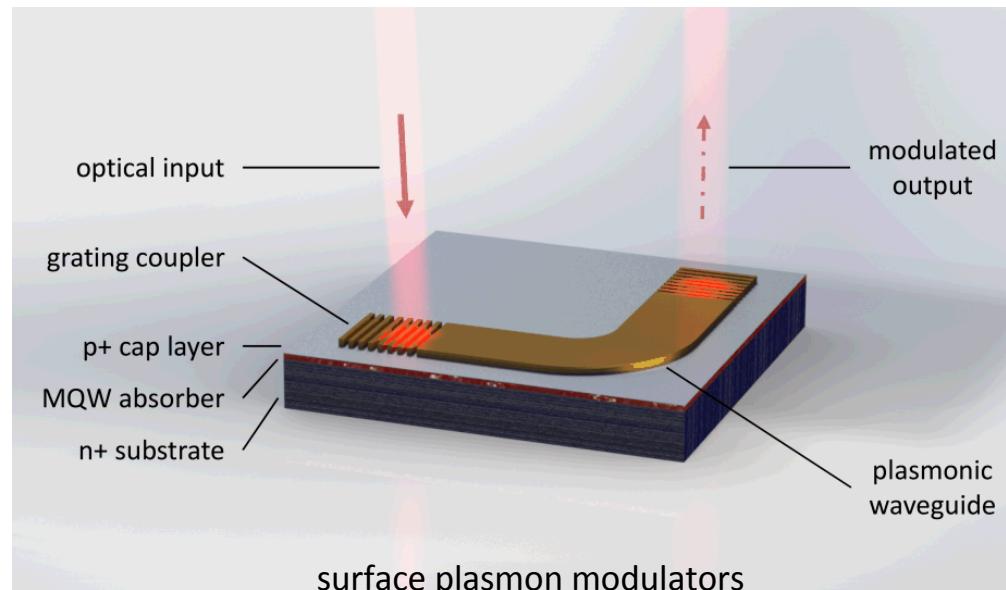
Near Infrared Active Plasmonics: Modulators, Emitters, Detectors

Plasmonics enables extreme field concentration and nanophotonic devices

- explosive field of study for the past decade (passive devices & MWIR/LWIR)
- devices promising for future photonic applications (speed, power, density)

Here we are investigating NIR active plasmonics in semiconductor materials

- leveraging strong resident photonics capabilities
- a wide range of practical devices that have not yet been explored



nanocavity emitters

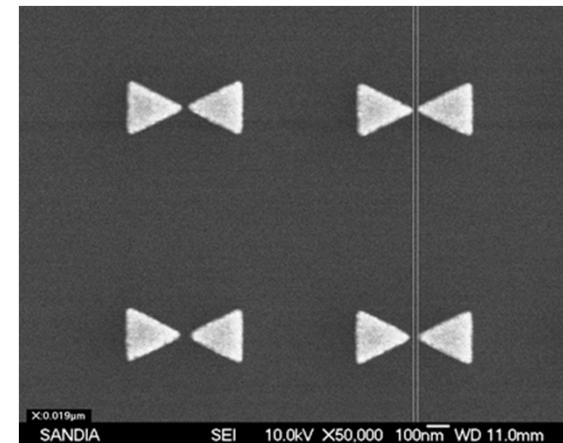
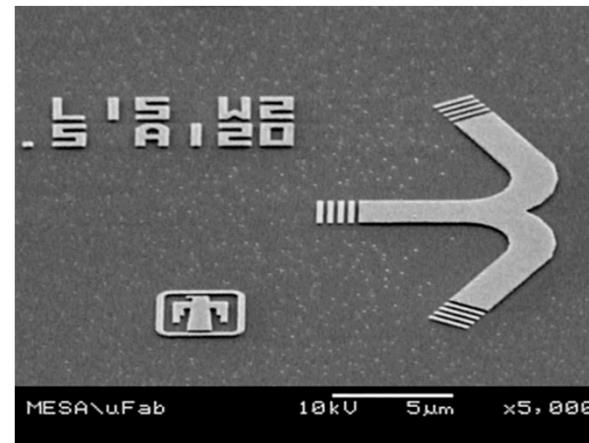
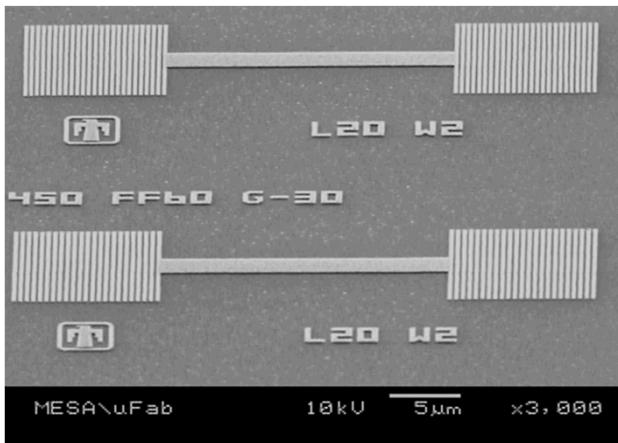
Nanofabrication of III-V Active Plasmonics

Growth and fabrication in Sandia's MESA and CINT nanofabrication facilities

- epitaxial growth on GaAs, GaSb, and InP by MBE and MOCVD
- patterning using a combination of contact and e-beam lithography
- standard III-V processing using wet/dry etch, metallization, anneal, etc.

Nanoscale devices under study

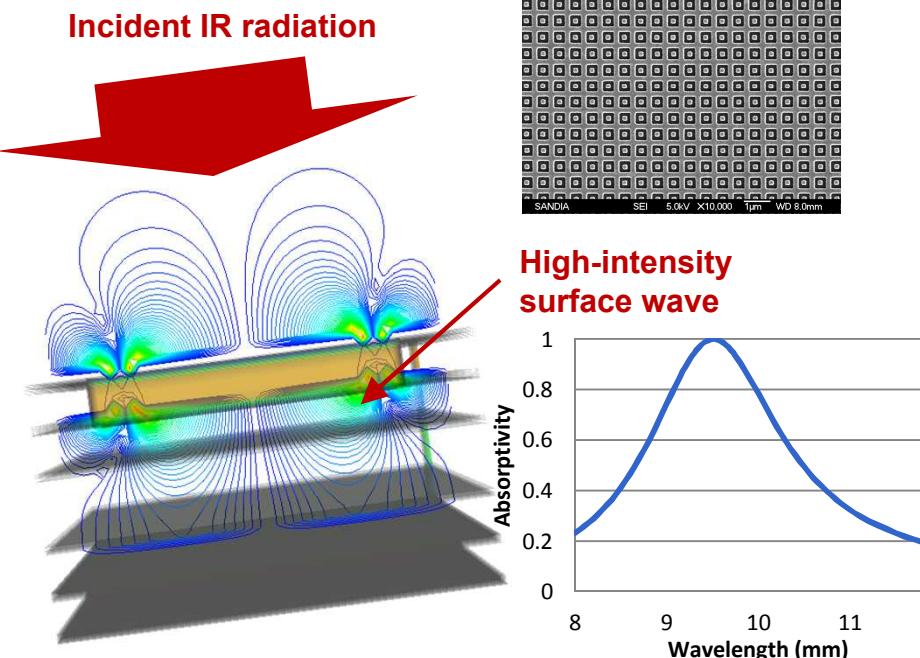
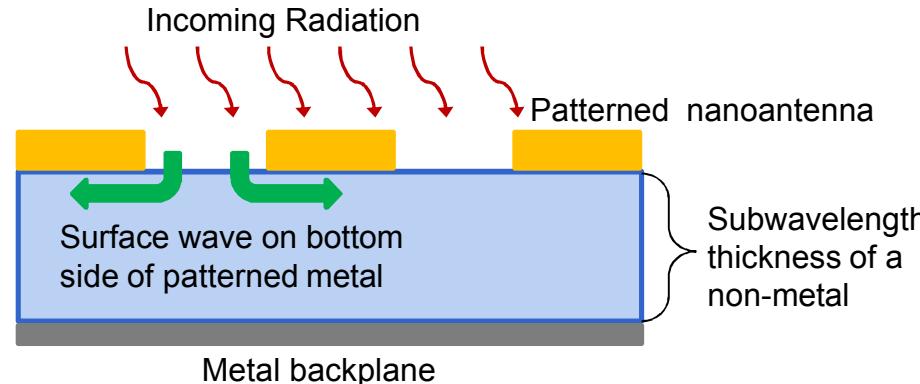
- modulators, nanoemitters, plasmonic crystals
- surface-normal grating couplers with varying fill factor, pitch, thickness
- waveguide bends, splits, dot waveguides, concentrators, gap antennas



active nanoplasmonic devices fabricated on compound semiconductors

Nanoantenna-Enabled Thin Detectors

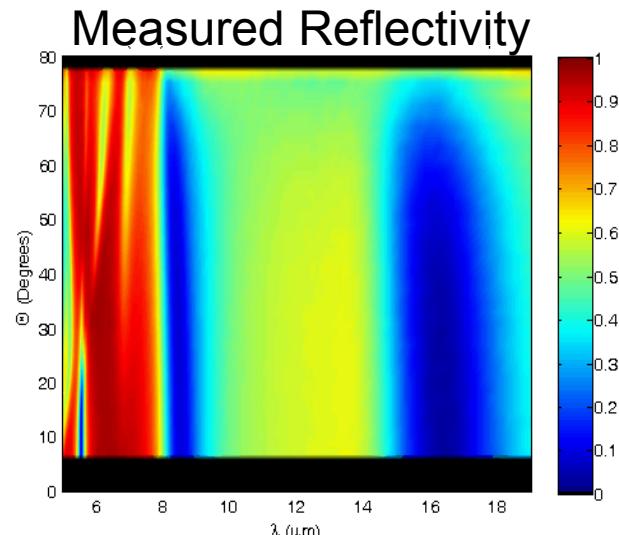
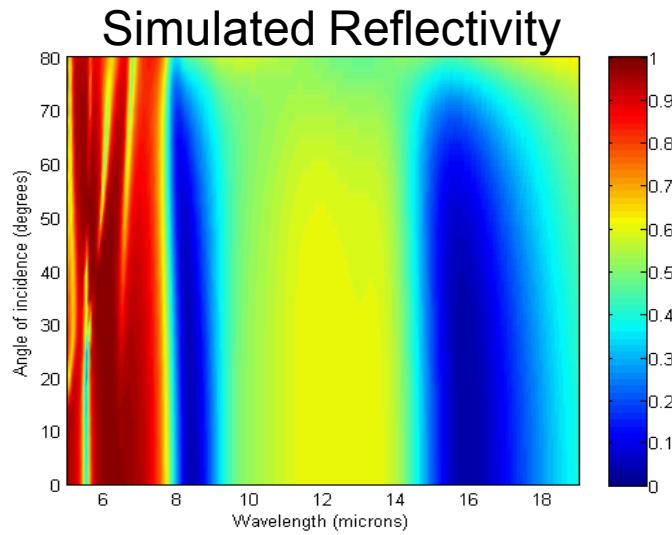
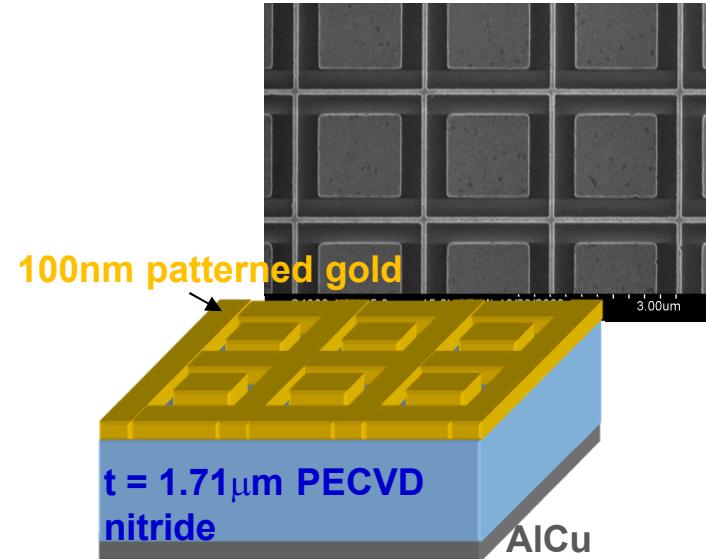
What is a nanoantenna?



- Nanoantennas are a fundamental technology that spans numerous sensor types
- Nanoantennas are an enabling technology for new applications such as 2D materials
- A nanoantenna is a distributed energy conversion device: the entire surface is the device
- A nanoantenna converts incoming radiation to a surface wave with energy confined to a small volume under the nanoantenna
- This confinement is what enables us to look at interesting applications
- The pattern is subwavelength, with many nanoantenna periods per device pixel. This pattern may be changed on a pixel-to-pixel basis allowing adjacent pixels to have different spectral or polarization response
- Our IR devices are enhanced by, or completely reliant on, the radiation conversion achieved by the nanoantenna

Background: Perfect Absorbers

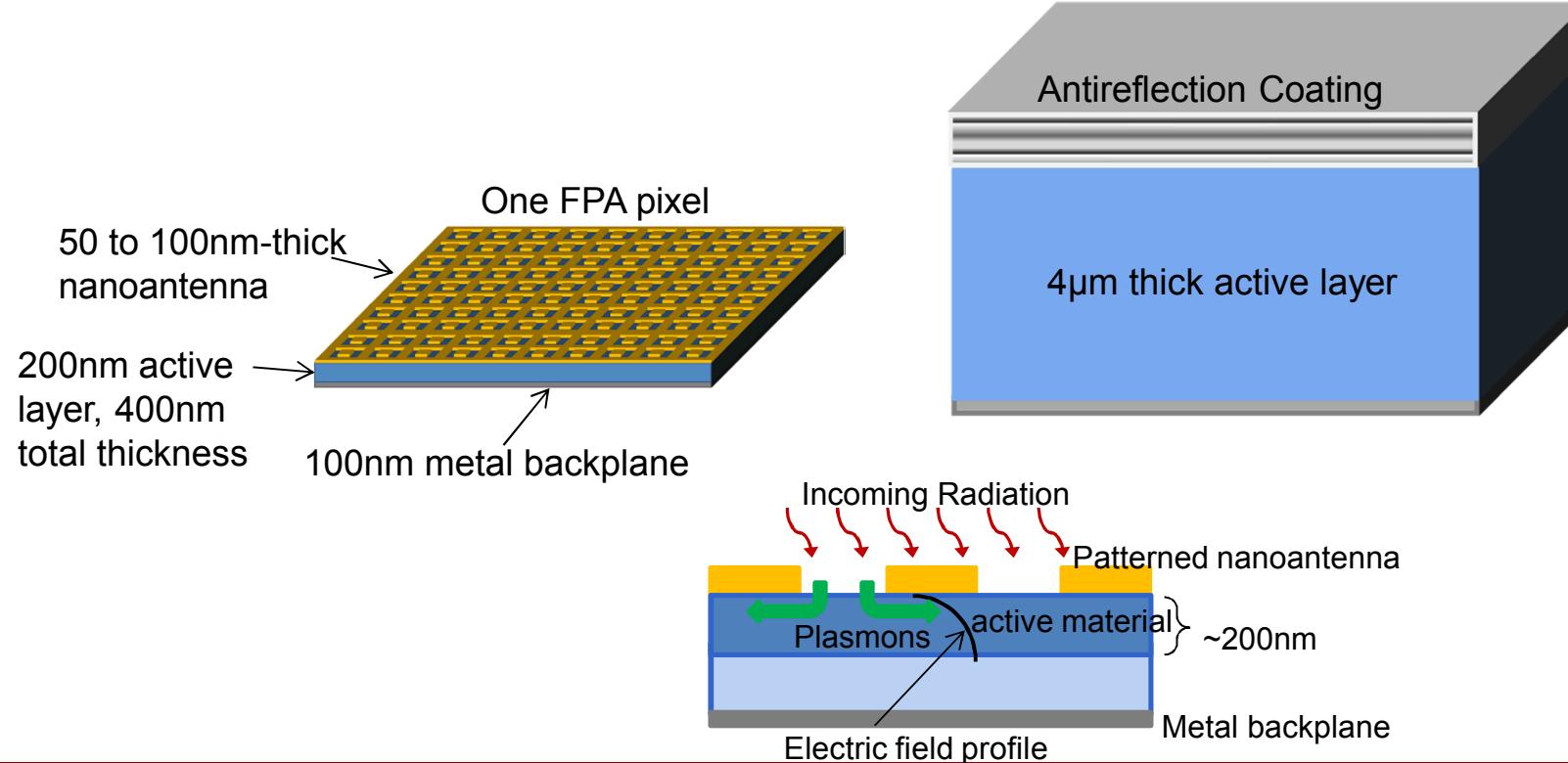
- We designed and made a dual-band perfect absorber.
- Excellent agreement between simulation and measurement → Great confidence in our models.
- Measured absorption of 99% in two bands.
- If we can absorb it, why not use that energy?



Incorporation with Existing Detector Materials in the Midwave

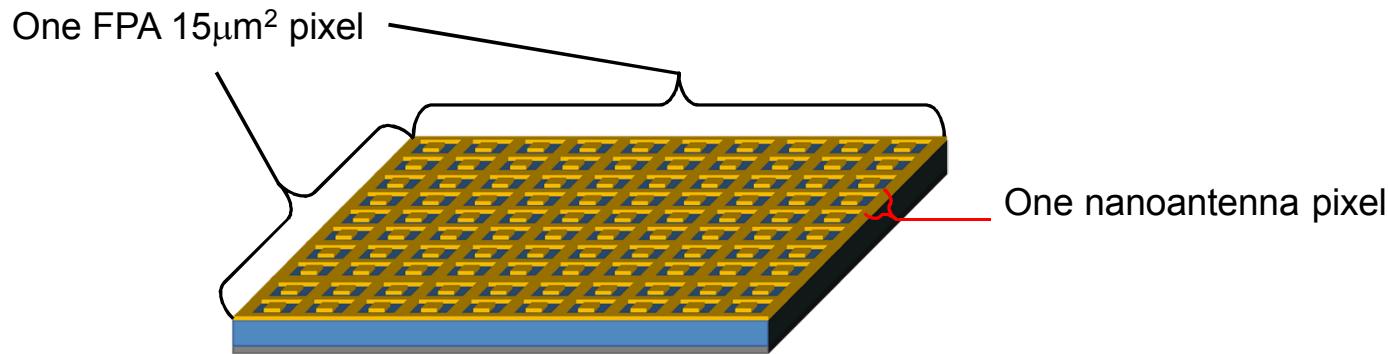
Integrate subwavelength nanoantenna with active material (MCT or InGaSb) for high-performance focal plane array (FPA).

Using dense fields to thin the active region.

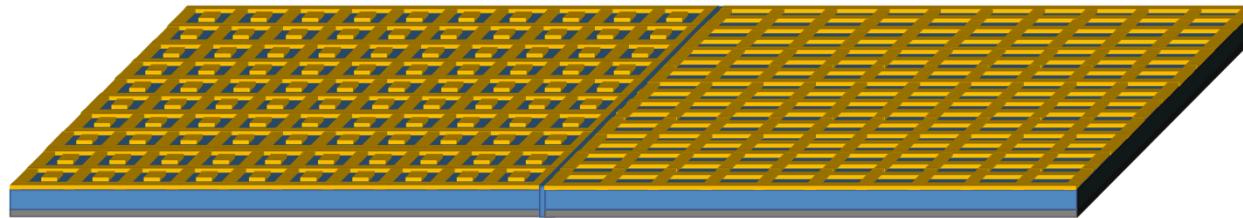


Advantages of the Nanoantenna Structure

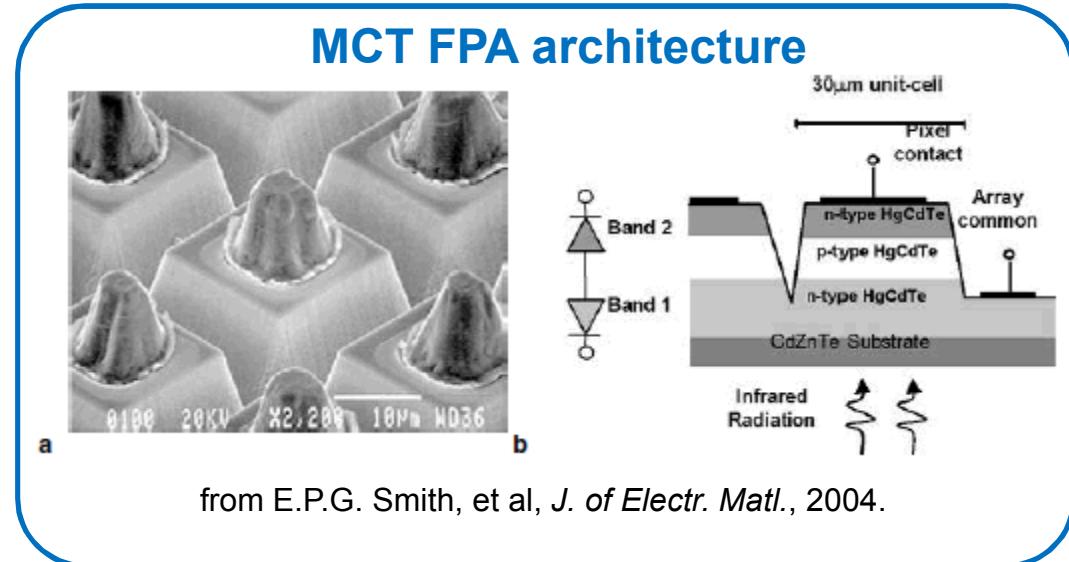
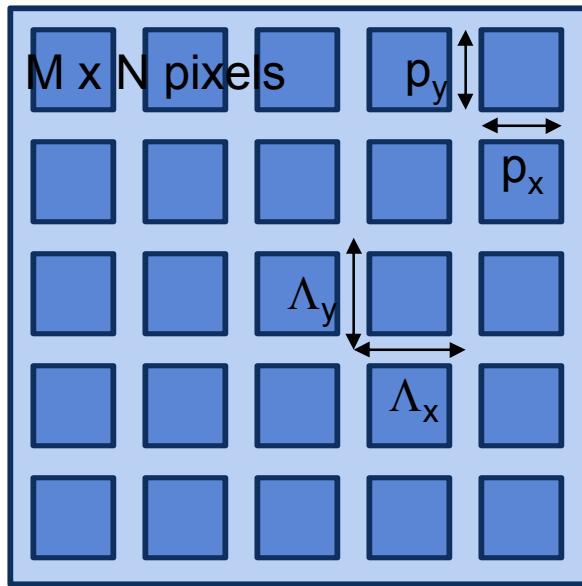
- Top and bottom contacts allow direct connection.
- Filtering can be changed from FPA pixel-to-pixel simply by changing the antenna pattern (Spectral or polarization). This is difficult to do with thin films.
- Small antenna unit cell allows multiple unit cells per FPA pixel (for broadband).



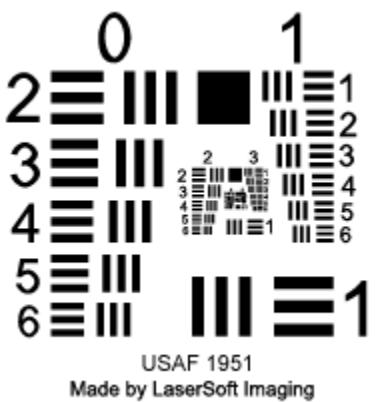
Two adjacent FPA pixels with different functionality.



Maximizing Active Area Improves MTF and Signal



$$MTF(f_x, f_y) = [\text{sinc}((M \cdot \Lambda_x) \cdot f_x, (N \cdot \Lambda_y) \cdot \eta) * \text{comb}(\Lambda_x \cdot f_x, \Lambda_y \cdot f_y)] \cdot \text{sinc}(p_x \cdot f_x, p_y \cdot f_y)$$



Ideally for the mathematical MTF function, we want Λ_x , Λ_y and p_x , p_y as small as possible to maximize the MTF.

This is clearly impossible, but we can make Λ_x and Λ_y as small as possible for a given p_x and p_y .

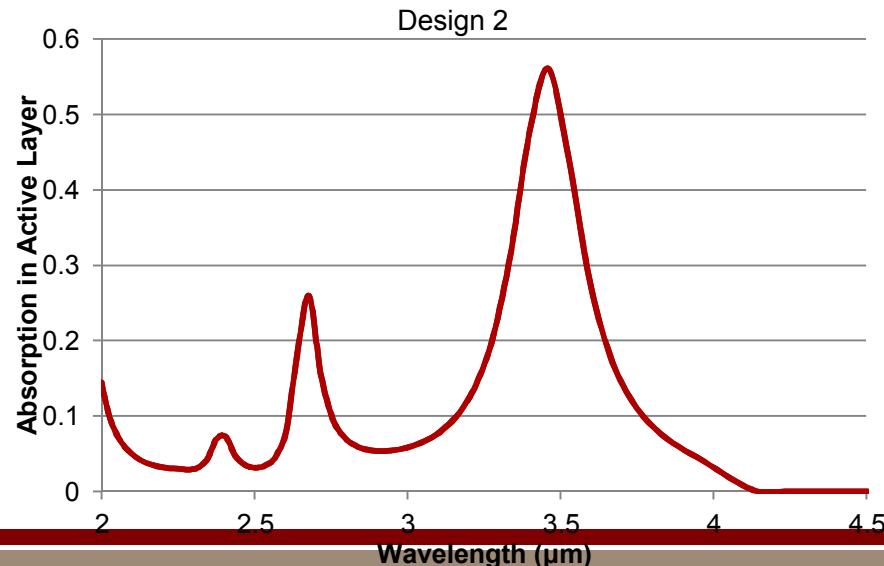
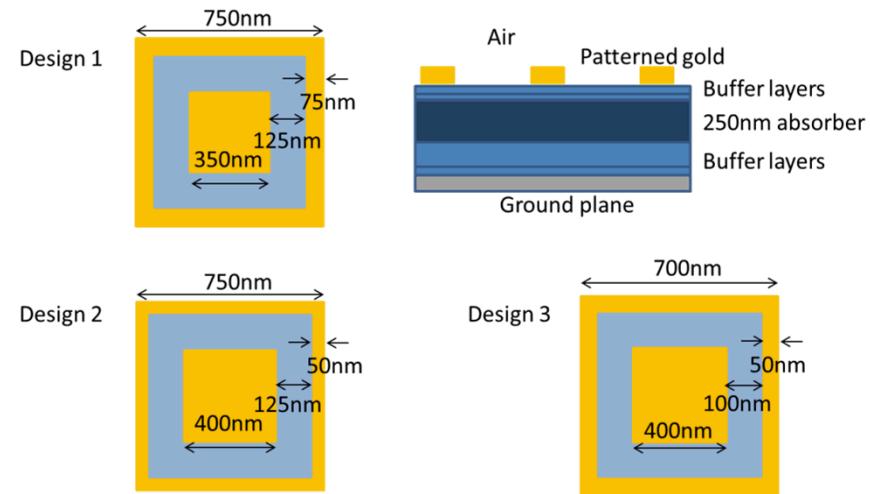
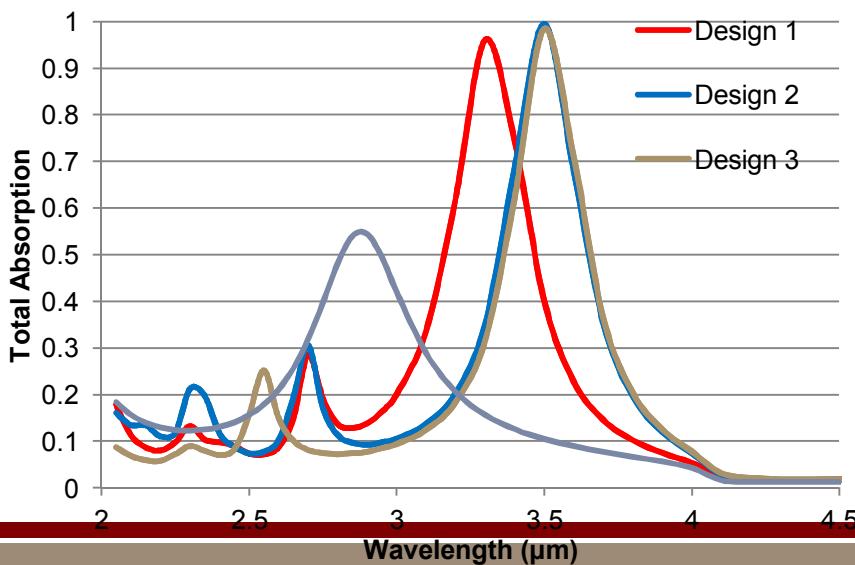
Our architecture gives us near 100% fill factor.

Simulation of InAsSb Design

Designs for peak responsivity in the $3.25\mu\text{m}$ to $3.5\mu\text{m}$ range.

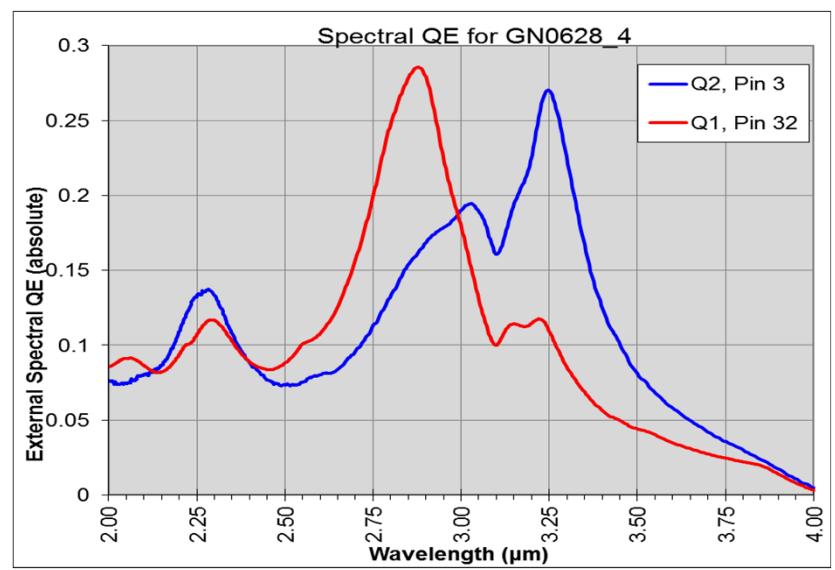
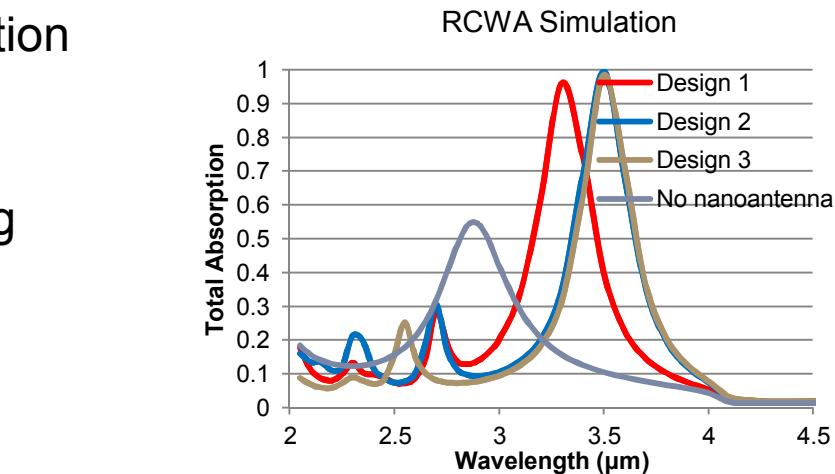
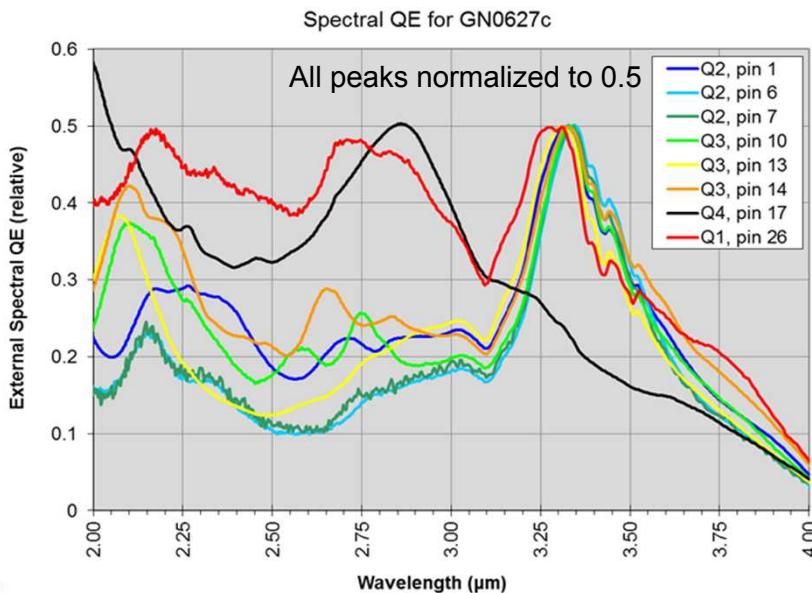
Three designs were fabricated with different patterns but similar peak resonances.

Designs were not optimized to maximize absorption in the active layer.



Nanoantenna-Enhanced InAsSb Detector Results

- Epitaxial growth of two designs for integration with NA for test/ evaluation.
- Successful fabrication of detectors with integration of NAs using a flip-chip bonding process and selective substrate removal.
- Room for optimization in modeling and in characterization procedures.

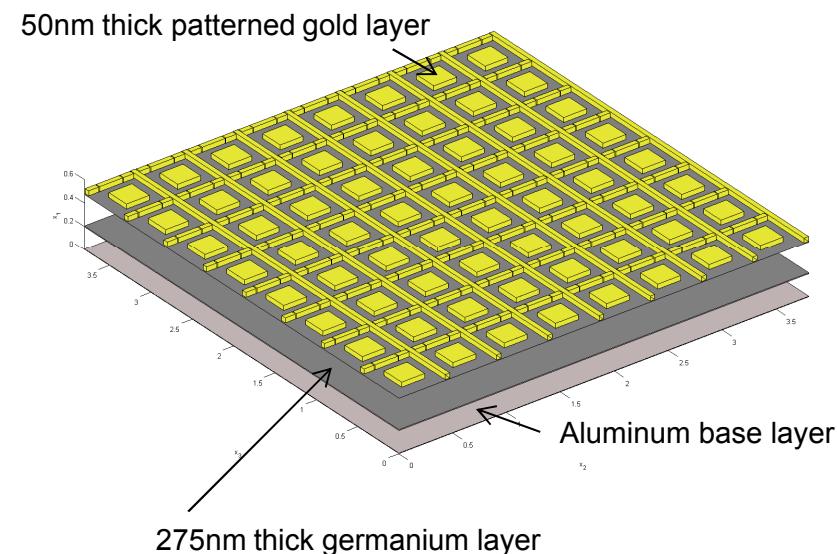
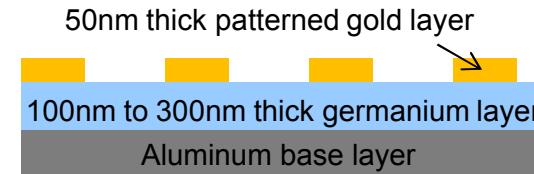
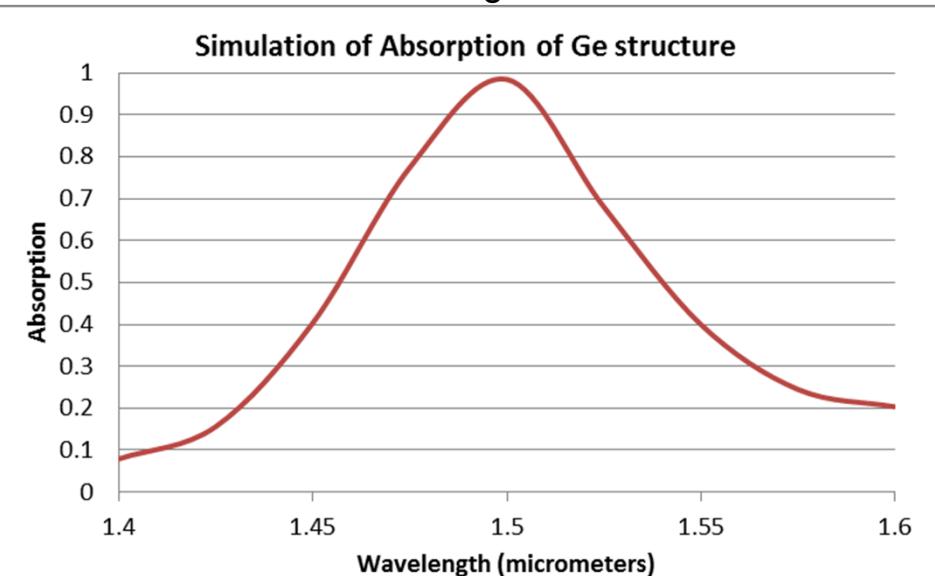


Germanium Detector

As with the MWIR designs, this one involves a detection material between two metal layers. Since it is for the near-IR, the detector layer is quite thin. The metal top and bottom layers act as contacts.

As it is thin, it is very fast as carriers move to a metal electrode quickly. Since the metal wire grid is not a large solid piece of metal, the capacitance should also be low.

We designed and simulated a structure with dimensions below to work at $1.5\mu\text{m}$. This is in the telecommunications wavelength band.

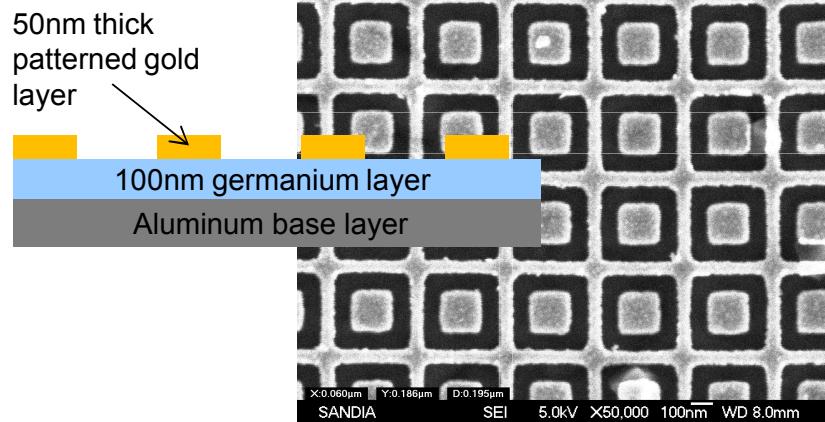


Period of nanoantenna = 475nm
Width of continuous gold bars = 50nm

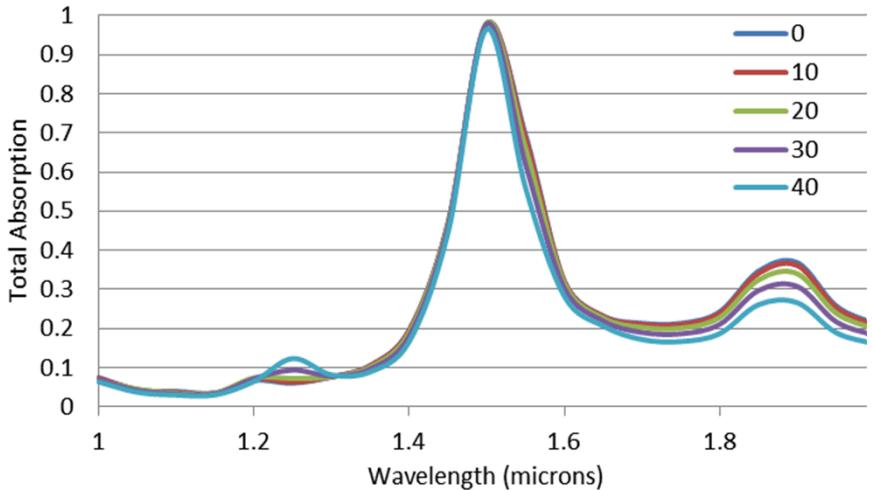
Germanium Detector Design

There is virtually no change from normal out to 40° in the 100nm thick design. In any practical imaging system, this is more than enough.

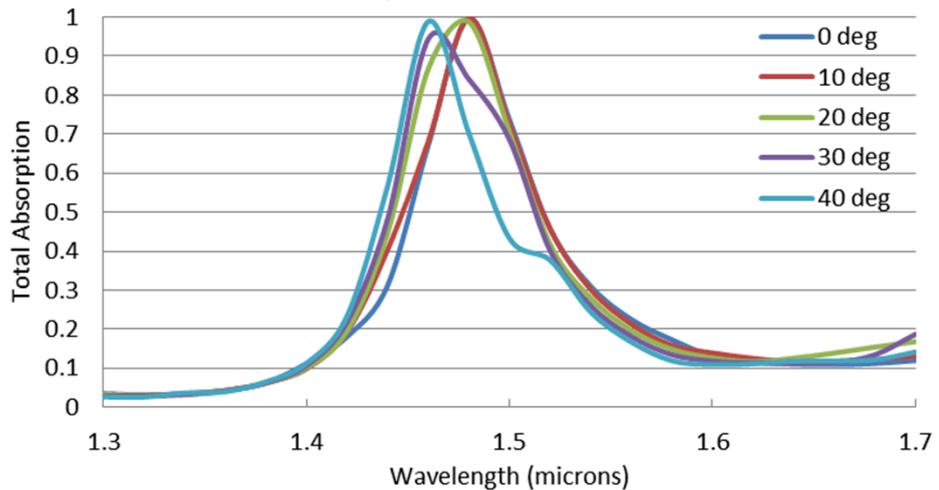
In the 275nm-thick design we see a change in peak wavelength between 20° and 30°.



Function of angle: 100nm Ge layer, 400nm period



Function of angle: 275nm Ge layer, 450nm period



Graphene Detectors: *Bilayer* Graphene Tunability



nature

Vol 459 | 11 June 2009 | doi:10.1038/nature08105

LETTERS

Direct observation of a widely tunable bandgap in bilayer graphene

Yuanbo Zhang^{1*}, Tsung-Ta Tang^{1*†}, Caglar Girit¹, Zhao Hao^{2,4}, Michael C. Martin², Alex Zettl^{1,3}, Michael F. Crommie^{1,3}, Y. Ron Shen^{1,3} & Feng Wang^{1,3}

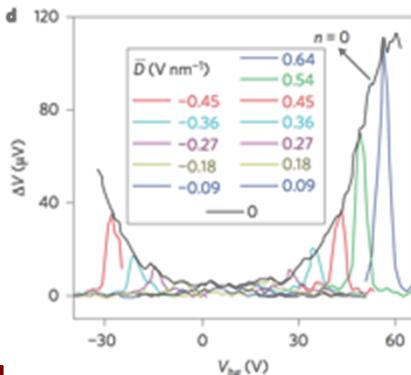
ARTICLES

PUBLISHED ONLINE: 3 JUNE 2012 | DOI: 10.1038/NNANO.2012.88

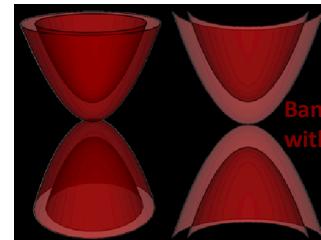
nature
nanotechnology

Dual-gated bilayer graphene hot-electron bolometer

Jun Yan^{1,2}, M-H. Kim^{1,2}, J. A. Elle^{2,3}, A. B. Sushkov^{1,2}, G. S. Jenkins^{1,2}, H. M. Milchberg^{2,3}, M. S. Fuhrer^{1,2*} and H. D. Drew^{1,2}

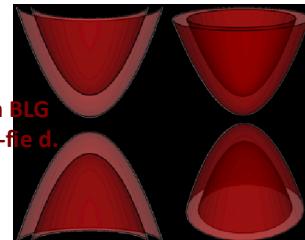


BLG: E-Field=0

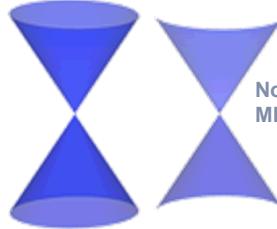


Bandgap opens in BLG with transverse E-field.

BLG: E-Field>0

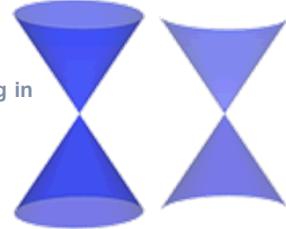


Mono: E-Field=0



No bandgap opening in MLG with E-field

Mono: E-Field>0

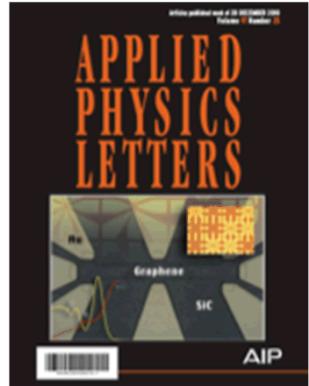


Problems:

1. Scalability
2. Low absorption
3. Multiphysics problem

Approach: Combination of Technologies

Scalability: Wafer-Scale BLG



NANO
LETTERS

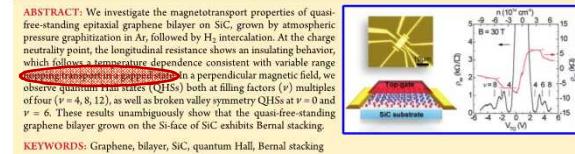
Magnetotransport Properties of Quasi-Free-Standing Epitaxial Graphene Bilayer on SiC: Evidence for Bernal Stacking

Kayoung Lee,¹ Seyoung Kim,¹ M. S. Points,¹ K. Keechim,¹ Tatsuke Ochiai,² and E. Tutuc^{*1}

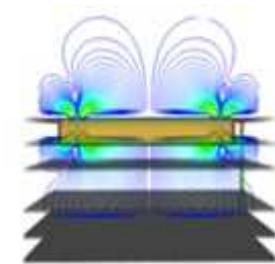
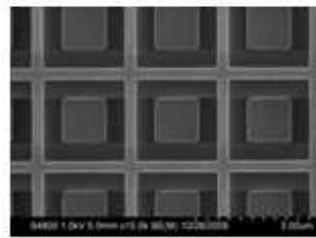
¹Microelectronics Research Center, The University of Texas at Austin, Austin, Texas 78758, United States

²Sandia National Laboratories, Albuquerque, New Mexico 87185, United States

¹ Supporting Information



Low Absorption: Nanoantennas



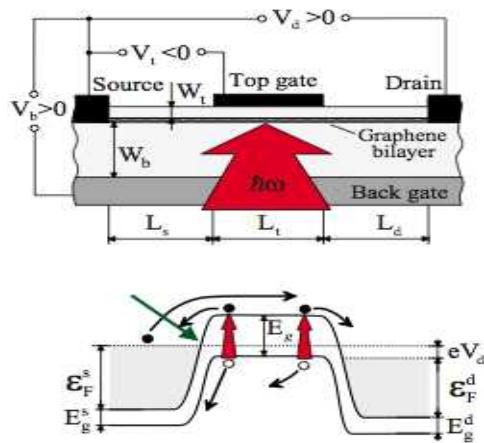
Nanoantenna-Enabled Midwave Infrared Focal Plane Arrays

David W. Peters*, Charles M. Reinke, Paul S. Davids, John F. Klem, Darin Leonhardt, Joel R. Wendt, Jin K. Kim, Sally Samora

Sandia National Laboratories, P.O. Box 5800, Albuquerque, NM, USA 87185-1082

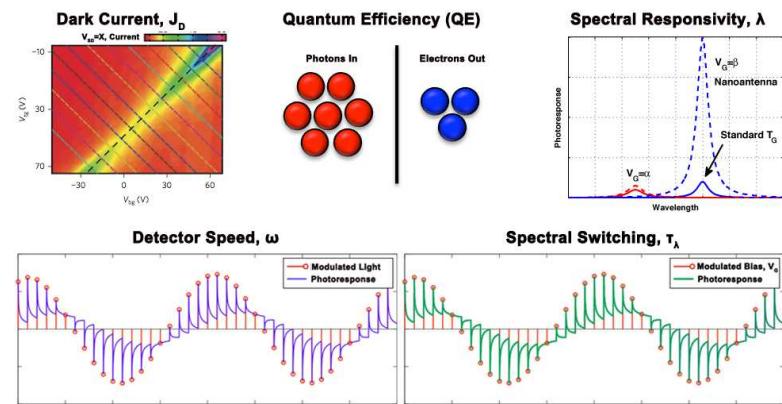
Proc. of SPIE Vol. 8353 83533B-1

Phenomenon: PhotoFET

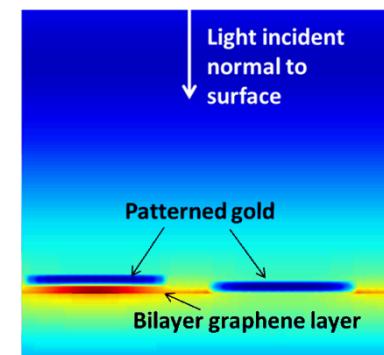
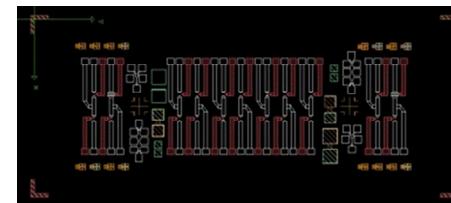
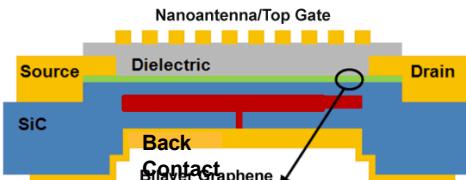
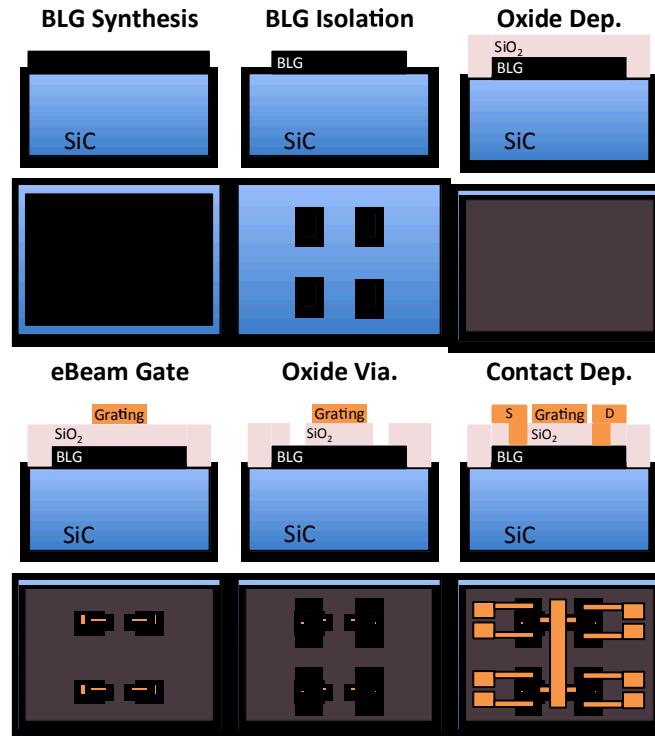


Ryzhii et al. PRB (79) 245311. 2009

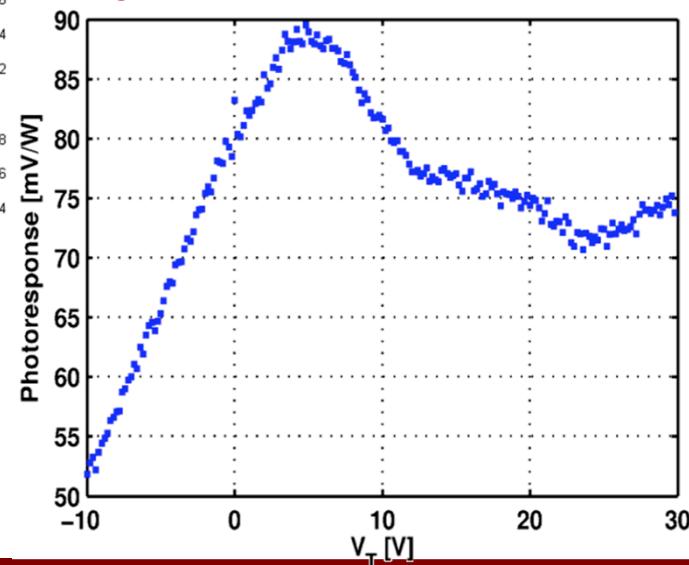
Next Steps: Technology Maturation



Graphene Detector: Early Fab and Results



- Scalable fabrication using “standard” techniques
- Multiple operational devices on a chip
- Opens path towards arrays
- Developed an improved understanding of the graphene/SiC interface



Devices show bias dependent tunability with a signal enhanced by nanoantennas.

Nanophotonics is an integral part of Sandia MESA research and fabrication.

- Plasmonic devices.
- Infrared detectors.
- New materials such as graphene and pyrolyzed carbon.

Nanoantennas offer methods of enhancement in traditional and new detector platforms.

- InAsSb detectors in the MWIR.
- Germanium detectors in the Near-IR.
- Graphene detectors that offer new capabilities.

Extra Slides

Si Photonics Publications in FY14

- J. A. Cox, A.L. Lentine, Douglas C. Trotter, and Andrew L. Starbuck, "Control of integrated micro-resonator wavelength via balanced homodyne locking," *Opt. Express* **22**, 11279-11289 (2014)
- R. Aguinaldo, A. Forencich, C. DeRose, A. Lentine, D. C. Trotter, Y. Fainman, G. Porter, G. Papen, and S. Mookherjea, "Wideband silicon-photonic thermo-optic switch in a wavelength-division multiplexed ring network," *Opt. Express* **22**, 8205-8218 (2014)
- J. A. Cox, A.L. Lentine, D. J. Savignon, R. D. Miller, D. C. Trotter, and A. L. Starbuck, "Very Large Scale Integrated Optical Interconnects: Coherent Optical Control Systems with 3D Integration," in *Advanced Photonics for Communications*, OSA Technical Digest (online) (Optical Society of America, 2014), paper IM2A.1.
- C. DeRose, "Integrated RF Silicon Photonics from High Power Photodiodes to Linear Modulators," in *Advanced Photonics for Communications*, OSA Technical Digest (online) (Optical Society of America, 2014), paper IW2A.1.
- D.A. Bender ; C. T. DeRose ; A. Starbuck ; J. C. Verley and M. W. Jenkins, "Precision laser annealing of silicon devices for enhanced electro-optic performance", *Proc. SPIE* 8967, *Laser Applications in Microelectronic and Optoelectronic Manufacturing (LAMOM) XIX*, 89670S (March 6, 2014).
- J. A. Cox, A. L. Lentine, D. J. Savignon, D. Trotter, and A. Starbuck, "Wavelength Control of Resonant Photonic Modulators with Balanced Homodyne Locking," in *CLEO: 2014*, OSA Technical Digest (online) (Optical Society of America, 2014), paper STh4M.7.
- C.T. DeRose, R. Kekatpure, A. Starbuck, A. Pomerene and A. L. Lentine, "A CMOS Compatible External Heater-Modulator", *IEEE Opt. Interconnect Conf.*, MC3, pp.17-18, May 2014.
- C.T. DeRose, N.J. Martinez, R.D. Kekatpure, W.A. Zortman, A.L. Starbuck, A. Pomerene and A. L. Lentine, "Thermal Crosstalk Limits for Silicon Photonic DWDM Interconnect", *IEEE Opt. Interconnect Conf.*, WC5, pp.125-126, May 2014.
- T. Iatchu, M. Pochet, N.G. Usechak, C. DeRose, A. L. Lentine, D.C. Trotter, and W. Zortman, "Power-Penalty Comparison of Push-Pull and Traveling-Wave Electrode Silicon Mach-Zehnder Modulators", *IEEE Opt. Interconnect Conf.*, MC7, pp.25-26, May 2014.
- R. Aguinaldo, A. Forencich, C. DeRose, A. L. Lentine, A. Starbuck, Y. Fainman, G. Porter, G. Papen, S. Mookherjea, "Characterization of a silicon-photonic wideband switch in UCSD's MORDIA ring network", *IEEE Opt. Interconnect Conf.*, TuD4, pp.102-103, May 2014.
- R. Aguinaldo, P.O. Weigel, H. Grant, C. DeRose, A. L. Lentine, A. Pomerene, A. Starbuck, S. Mookherjea, "Characterization of a silicon-photonic multi-wavelength power monitor", *IEEE Opt. Interconnect Conf.*, WD5, pp.139-140, May 2014.
- 2 at Integrated Photonics Research Conf., 5 at Optical Interconnect Conf., 1 SPIE, 1 CLEO; 2 journals.

Selected Sandia's Photonics Patents



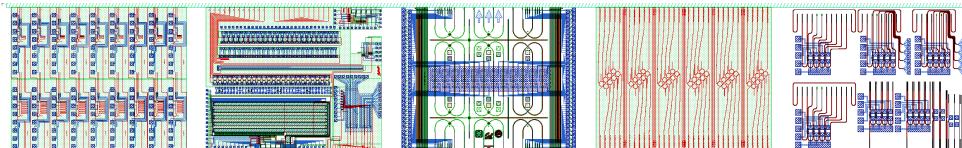
Silicon Photonics

- U.S. Patent 7616850, Wavelength-Tunable Optical Ring Resonators (SD 10791.0)
- U.S. Patent 7941014, Optical Waveguide Device With An Adiabatically-Varying Width (SD 11104.0)
- U.S. Patent 7983517, Wavelength-Tunable Optical Ring Resonators (SD 10791.1)
- U.S. Patent 8027587 , Integrated Optic Vector-Matrix Multiplier(SD 10237.1)
- U.S. Patent 8610994, Silicon Photonics Thermal Phase Shifter With Reduced Temperature Range (SD 11837.0)
- U.S. Patent 8615173, Systems For Active Control of Integrated Resonant Optical Device Wavelength (SD 11555.0)
- U.S. Patent 8600200, Nano-Optomechanical Transducer (SD 11508.0)
- U.S. Patent 8625939, Ultralow Loss Cavities and Waveguides Scattering Loss Cancellation (SD 11631.0)
- U.S. Patent 8822959, Method And Apparatus For Optical Phase Error Correction (SD 12024.0)

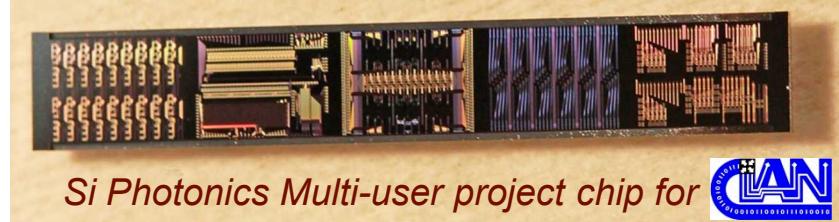
Plasmonics for Infrared Sensors

- U.S. Patent 8452134, Frequency Selective Infrared Sensors (SD 11433.0)
- U.S. Patent 8750653, Infrared Nanoantenna Apparatus and Method for the Manufacture thereof (SD 12379.0, SD 12539.0)
- 9 issued patents in Si photonics and 2 in nano-antenna related areas (4 issued in FY2014)
- 21 additional patents pending (9 patents filed in FY2014)

SiP Multi-User Wafer Project



Cornell UCSD Berkeley Arizona Berkeley



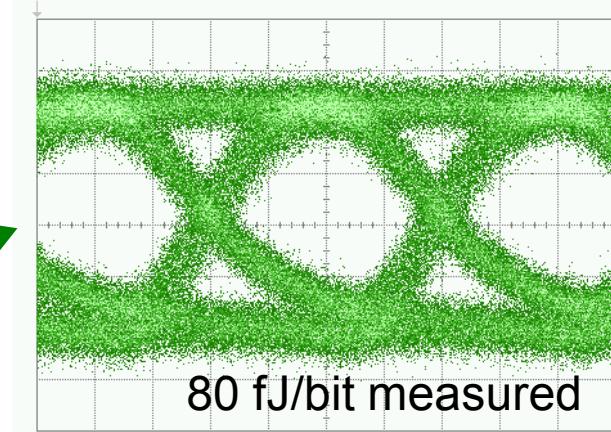
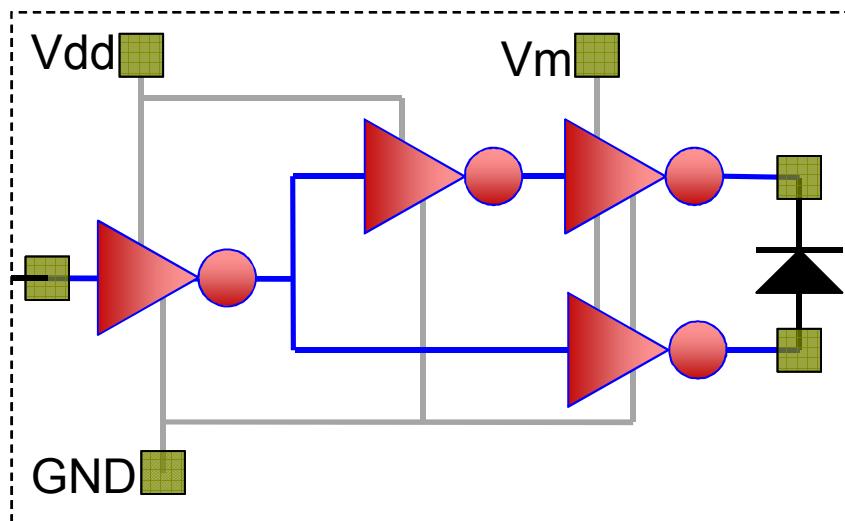
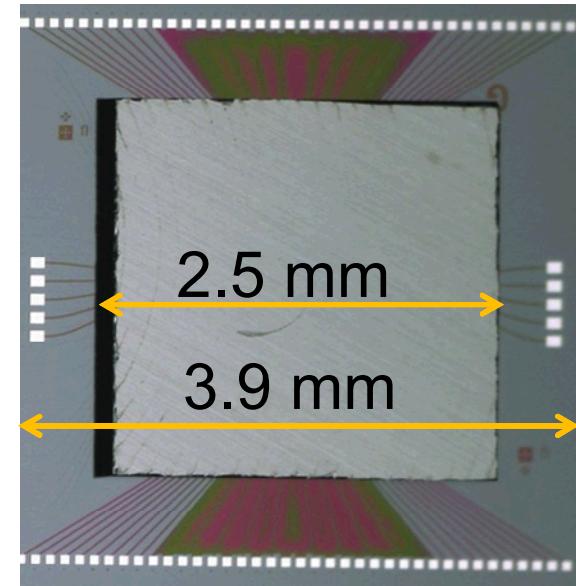
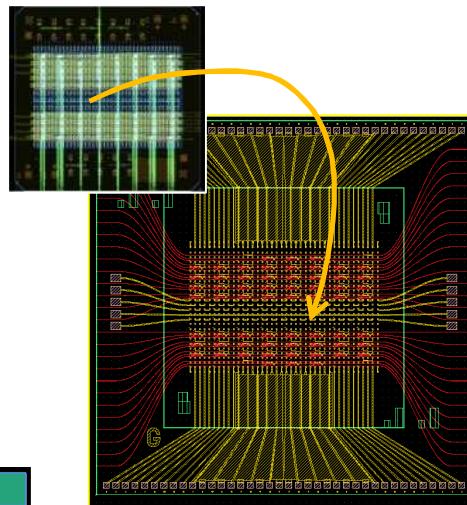
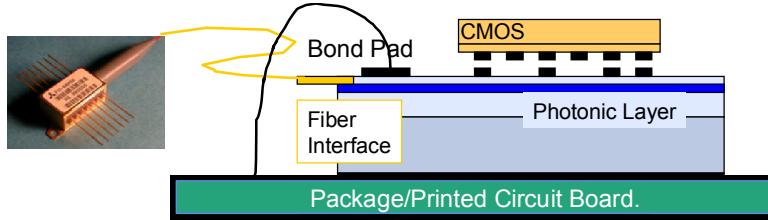
Si Photonics Multi-user project chip for 

- Successfully completed 3 milestone deliverables to NSF CIAN (Center of Integrated Access Networks) universities
 - Passive chips
 - Active chips (with P/N junctions for modulators, etc.)
 - Active chips with Germanium (with integrated photo detectors)
- On-going discussions for next collaborations (to include CUDOS and University of Bristol)
- Active planning in Photonics Manufacturing Innovation (IMI) led by DOD/AFRL (\$110M BAA anticipated in early Nov)

Electronics – Photonics Integration

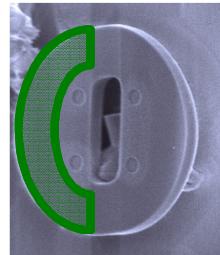
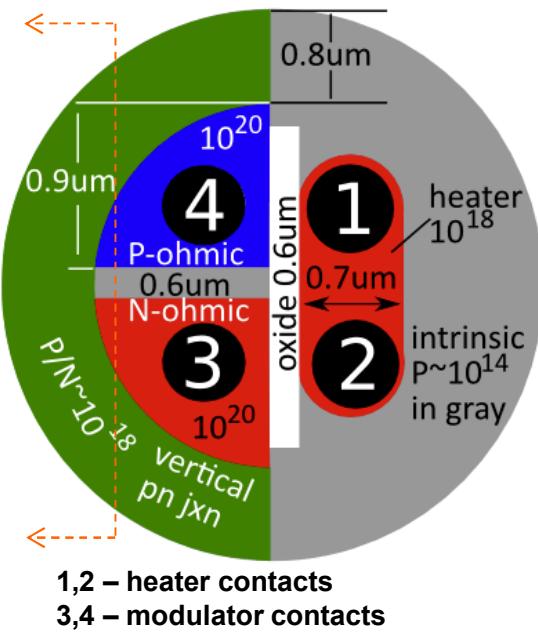
Heterogeneous Integration

- Independent optimization of electronics & photonics
- Challenge: Need high yields and small bond size

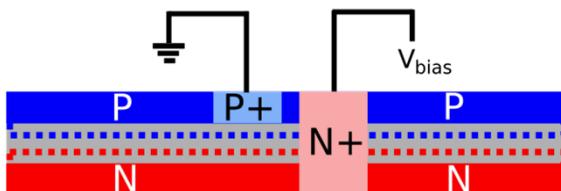
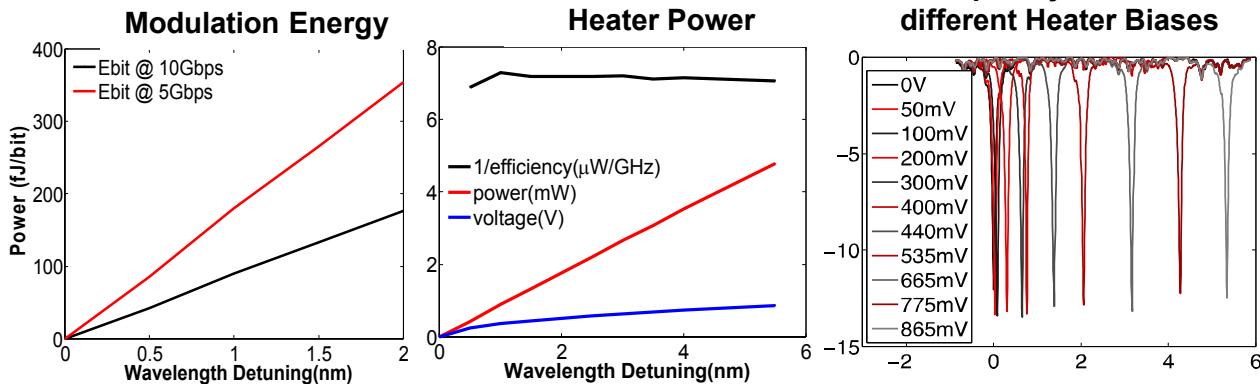


Modulated optical output at 5 Gbps

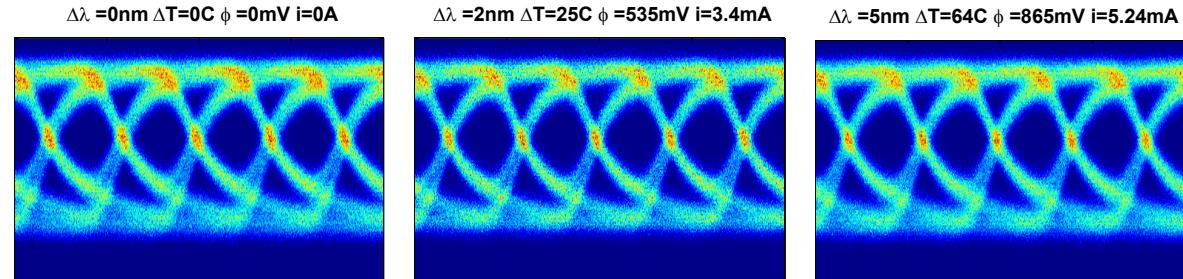
10Gbps Resonant Heater Modulator



- FSR covers entire C-band
- Low footprint of $\sim 14\mu\text{m}^2$, CMOS-compatible
- Differential signaling compatibility
- Lowest intrinsic tuning energy
 $7\mu\text{W/GHz}$ (0.7fJ/bit-GHz)



Cross-section of modulator with vertical P-N junction

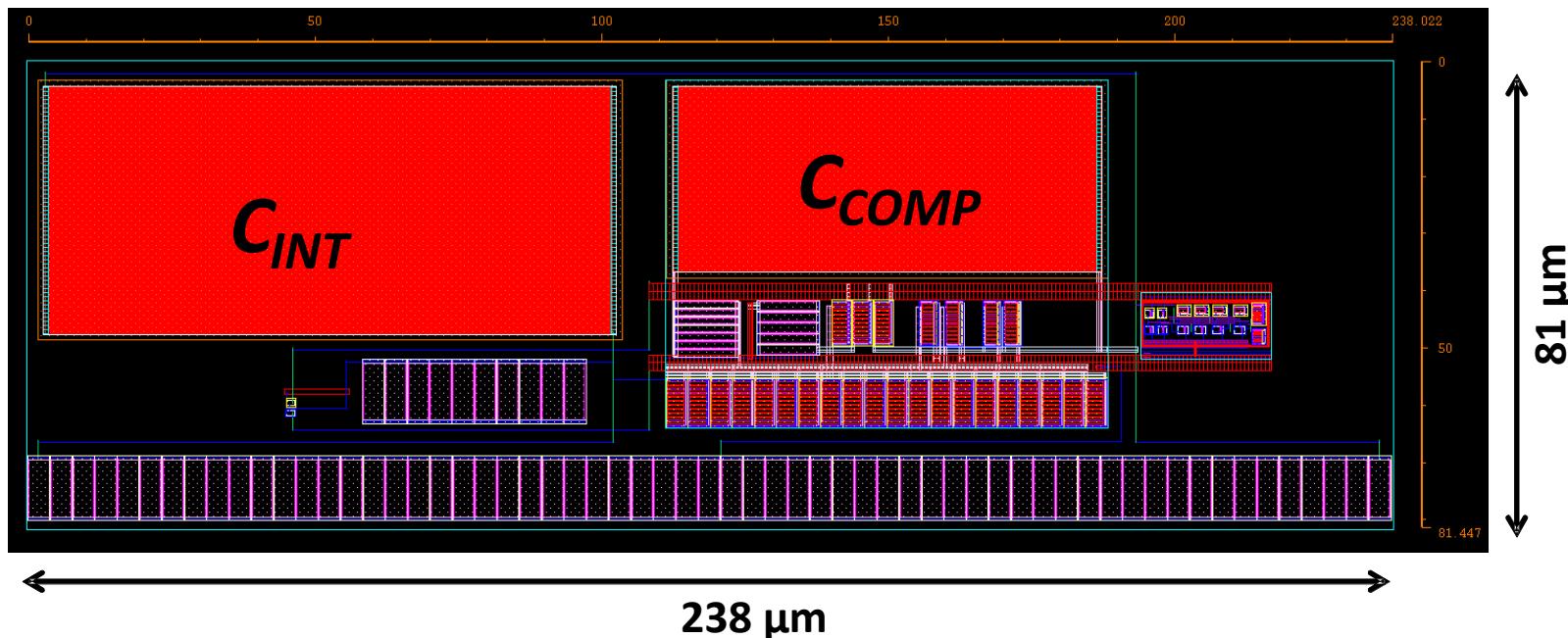


Similar eye diagrams achieved at different tuning temperatures

CMOS ASIC Design (under fab)

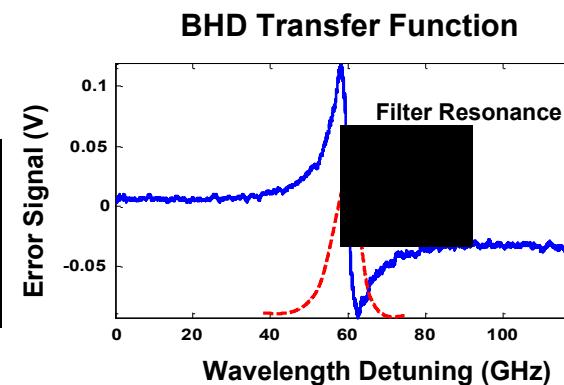
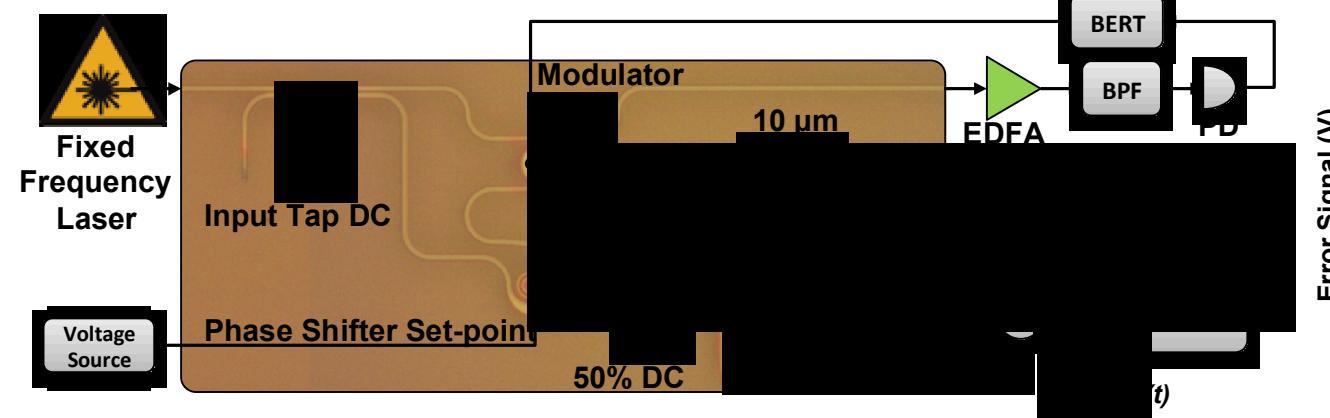
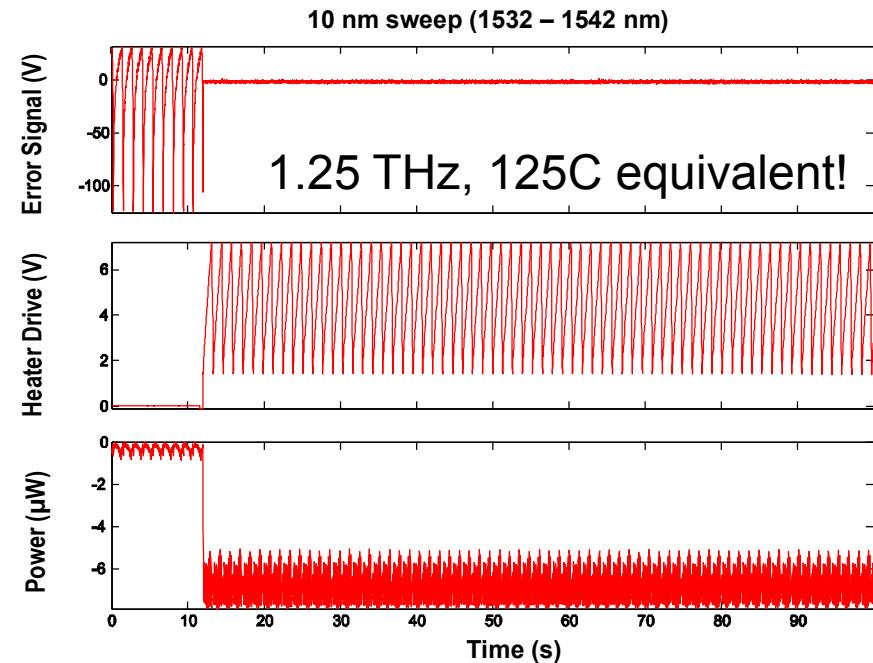
- **IBM 45 nm CMOS ASIC** designed at Sandia
- **Power consumption:** 1.07 mW (steady-state); 0.27 mW (TIA) and 0.8 mW (integrator) (30 – 100 fJ/bit @ 30Gbps-10Gbps) [1]
- **Heater time constant** → large integrator resistor and capacitor in loop filter
- **Heater driver:** Class-B “push-pull”
- **Inverter** implemented with analog switch network

[1] recent result by X. Zheng (OpX 2014)
200 μ W, 2600 μ m² for ‘power meter’ control



Stabilization of Modulators

- **Lock to zero:** No calibration or reference level needed for locking
- **Amplitude insensitive:** Locking point not influenced by optical intensity
- **Precision locking:** Resonator is not disturbed
- **Minimum circuit complexity:** Power and area consumption of control electronics is minimized



Sandia and MPW Fabrication



■ **SUMMIT V:**

5 layer polysilicon MEMS process

- Developed design manual, DRC, many MPWs over the last decade

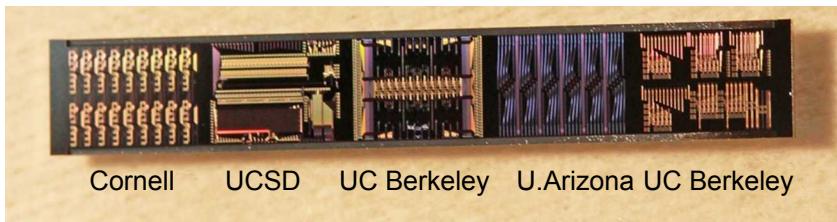
■ **CMOS7 Electronics:**

Rad-hard, mixed-signal ASIC/ViaArray

- 0.35um, 3.3V core, 3.3V I/O, Cadence, MPWs since 2009

■ **SPP1 Silicon Photonics Process:**

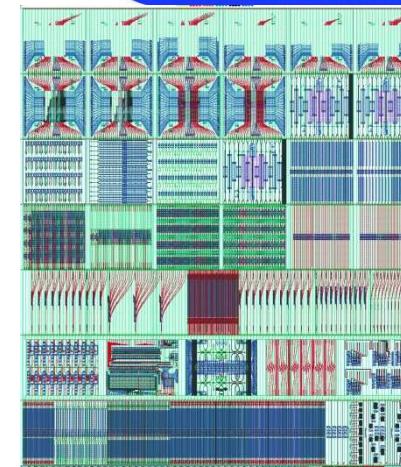
- 250nm Si/3000nm BOx
- fJ/bit mods, 45 GHz dets, filters, etc.
- SiN 2-layer guides/xovers
- Design manual, initial DRC, pilot MPW runs



4. TECHNOLOGY OVERVIEW



ries (SRL) has developed a Microsystems and Engineering Sciences located in a limited classified area. Trusted custom fabrication of silicon and technologies for digital, analog and mixed signal ICs is currently available. SRL produces micro-electronics components to support special DOE and SRS. Complex is designed to integrate the numerous scientific disciplines, robust, integrated **microsystems** and represents the center of SRL's research, development and prototyping activities. This suite of facilities by 400,000 square feet and includes **cleanroom** facilities, laboratories and laboratories.



LESS DETAILED

cess flow of are described in Table 5-1. The base process can be broken

